SGUS030F - APRIL 2000 - REVISED SEPTEMBER 2013

RAD-TOLERANT CLASS-V FLOATING-POINT DIGITAL SIGNAL PROCESSOR

Check for Samples: SMJ320C6701-SP

FEATURES

- Rad-Tolerant: 100-kRad (Si) TID
- SEL Immune at 89MeV-cm2/mg LET Ions
- QML-V Qualified, SMD 5962-98661
- Highest-Performance Floating-Point Digital Signal Processor (DSP) SMJ320C6701
 - 7-ns Instruction Cycle Time
 - 140-MHz Clock Rate
 - Eight 32-Bit Instructions/Cycle
 - Up to One GFLOPS Performance
 - Pin Compatible With 'C6201 Fixed-Point DSP
- SMJ: QML Processing to MIL-PRF-38535
- SM: Standard Processing
- Operating Temperature Ranges
 - 55°C to 115°C
 - 55°C to 125°C
- VelociTI[™] Advanced Very Long Instruction Word (VLIW) 'C67x CPU Core
 - Eight Highly Independent Functional Units:
 - Four ALUs (Floating and Fixed Point)
 - Two ALUs (Fixed Point)
 - Two Multipliers (Floating and Fixed Point)
 - Load-Store Architecture With 32
 32-Bit General-Purpose Registers
 - Instruction Packing Reduces Code Size
 - All Instructions Conditional
- Instruction Set Features
 - Hardware Support for IEEE Single-Precision Instructions
 - Hardware Support for IEEE Double-Precision Instructions
 - Byte Addressable (8-/16-/32-Bit Data)
 - 32-Bit Address Range
 - 8-Bit Overflow Protection
 - Saturation
 - Bit-Field Extract, Set, Clear

- Bit Counting
- Normalization
- 1M-Bit On-Chip SRAM
 - 512K-Bit Internal Program/Cache (16K 32-Bit Instructions)
 - 512K-Bit Dual-Access Internal Data (64K Bytes)
- 32-Bit External Memory Interface (EMIF)
 - Glueless Interface to Synchronous Memories: SDRAM and SBSRAM
 - Glueless Interface to Asynchronous Memories: SRAM and EPROM
- Four-Channel Bootloading Direct Memory Access (DMA) Controller With Auxiliary Channel
- 16-Bit Host-Port Interface (HPI)
 - Access to Entire Memory Map
- Two Multichannel Buffered Serial Ports (McBSPs)
 - Direct Interface to T1/E1, MVIP, SCSA Framers
 - ST Bus Switching Compatible
 - Up to 256 Channels Each
 - AC97 Compatible
 - Serial Peripheral Interface (SPI)
 Compatible (Motorola™)
- Two 32-Bit General-Purpose Timers
- Flexible Phase-Locked Loop (PLL) Clock Generator
- IEEE Std 1149.1 (JTAG (1)) Boundary Scan Compatible
- 429-Pin Ceramic Ball Grid Array (CBGA/GLP) and Ceramic Land Grid Array (CLGA/ZMB) Package Types
- 0.18-µm/5-Level Metal Process
 - CMOS Technology
- 3.3-V I/Os, 1.9 V Internal
- IEEE Std 1149.1-1990 Test Access Port and Boundary Scan Architecture



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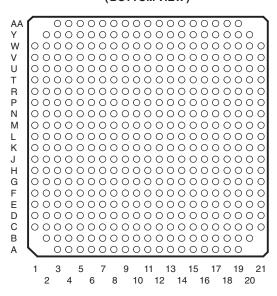
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Engineering Evaluation (/EM) Samples are Available (2)

(2) These units are intended for engineering evaluation only. They are processed to a non-compliant flow (e.g. No Burn-In, etc.) and are tested to a temperature rating of 25°C only. These units are not suitable for qualification, production, radiation testing or flight use. Parts are not warranted for performance over the full MIL specified temperature range of -55°C to 125°C or operating life.

GLP AND ZMB PACKAGES (BOTTOM VIEW)



DESCRIPTION

The SMJ320C67x DSPs are the floating-point DSP family in the SMJ320C6000 platform. The SMJ320C6701 ('C6701) device is based on the high-performance, advanced VelociTI™ very-long-instruction-word (VLIW) architecture developed by Texas Instruments (TI), making this DSP an excellent choice for multichannel and multifunction applications. With performance of up to 1 giga floating-point operations per second (GFLOPS) at a clock rate of 140 MHz, the 'C6701 offers cost-effective solutions to high-performance DSP programming challenges. The 'C6701 DSP possesses the operational flexibility of high-speed controllers and the numerical capability of array processors. This processor has 32 general-purpose registers of 32-bit word length and eight highly independent functional units. The eight functional units provide four floating-/fixed-point ALUs, two fixed-point ALUs, and two floating-/fixed-point multipliers. The 'C6701 can produce two multiply-accumulates (MACs) per cycle for a total of 334 million MACs per second (MMACS). The 'C6701 DSP also has application-specific hardware logic, on-chip memory, and additional on-chip peripherals.

The 'C6701 includes a large bank of on-chip memory and has a powerful and diverse set of peripherals. Program memory consists of a 64K-byte block that is user-configurable as cache or memory-mapped program space. Data memory consists of two 32K-byte blocks of RAM. The peripheral set includes two multichannel buffered serial ports (McBSPs), two general-purpose timers, a host-port interface (HPI), and a glueless external memory interface (EMIF) capable of interfacing to SDRAM or SBSRAM and asynchronous peripherals.

The 'C6701 has a complete set of development tools that includes a new C compiler, an assembly optimizer to simplify programming and scheduling, and a Windows™ debugger interface for visibility into source code execution.

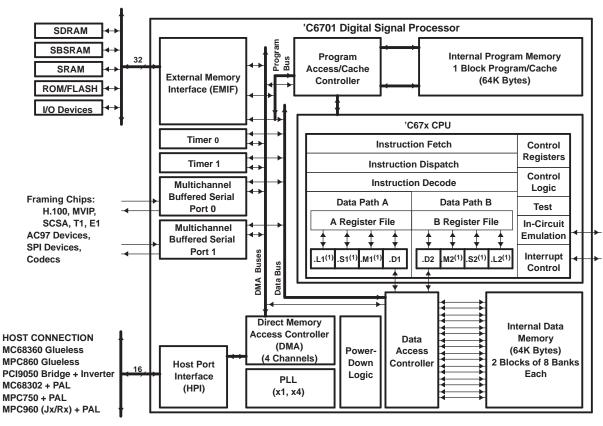
Device Characteristics

Table 1 provides an overview of the 'C6701 DSP. The table shows significant features of each device, including the capacity of on-chip RAM, the peripherals, the execution time, and the package type with pin count.

Table 1. Characteristics of 'C6701 Processors

CHARACTERISTICS	DESCRIPTION
Device Number	SMJ320C6701
On-Chip Memory	512K-bit Program Memory 512K-bit Data Memory (organized as 2 blocks)
Peripherals	2 Mutichannel Buffered Serial Ports (McBSP) 2 General-Purpose Timers Host-Port Interface (HPI) External Memory Interface (EMIF)
Cycle Time	7 ns at 140 MHz
Package Type	27 mm × 27 mm, 429-Pin BGA (GLP) and 429-Pin LGA (ZMB)
Nominal Voltage	1.9 V Core 3.3 V I/O

Functional and CPU Block Diagram



(1) These functional units execute floating-point instructions.



CPU Description

The CPU fetches VelociTI advanced very-long instruction words (VLIW) (256 bits wide) to supply up to eight 32-bit instructions to the eight functional units during every clock cycle. The VelociTI VLIW architecture features controls by which all eight units do not have to be supplied with instructions if they are not ready to execute. The first bit of every 32-bit instruction determines if the next instruction belongs to the same execute packet as the previous instruction, or whether it should be executed in the following clock as a part of the next execute packet. Fetch packets are always 256 bits wide; however, the execute packets can vary in size. The variable-length execute packets are a key memory-saving feature, distinguishing the 'C67x CPU from other VLIW architectures.

The CPU features two sets of functional units. Each set contains four units and a register file. One set contains functional units .L1, .S1, .M1, and .D1; the other set contains units .D2, .M2, .S2, and .L2. The two register files contain 16 32-bit registers each for the total of 32 general-purpose registers. The two sets of functional units, along with two register files, compose sides A and B of the CPU (see the functional and CPU block diagram and Figure 1). The four functional units on each side of the CPU can freely share the 16 registers belonging to that side. Additionally, each side features a single data bus connected to all registers on the other side, by which the two sets of functional units can access data from the register files on opposite sides. While register access by functional units on the same side of the CPU as the register file can service all the units in a single clock cycle, register access using the register file across the CPU supports one read and one write per cycle.

The 'C67x CPU executes all 'C62x instructions. In addition to 'C62x fixed-point instructions, the six out of eight functional units (.L1, .M1, .D1, .D2, .M2, and .L2) also execute floating-point instructions. The remaining two functional units (.S1 and .S2) also execute the new LDDW instruction which loads 64 bits per CPU side for a total of 128 bits per cycle.

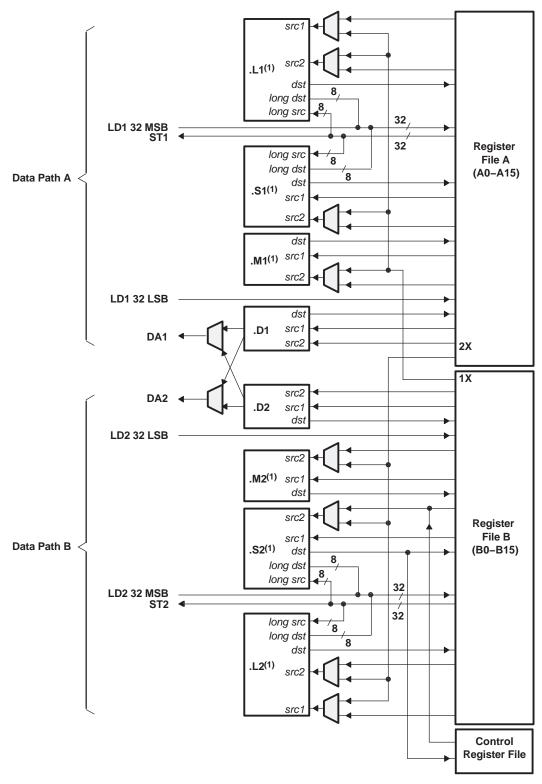
Another key feature of the 'C67x CPU is the load/store architecture, where all instructions operate on registers (as opposed to data in memory). Two sets of data-addressing units (.D1 and .D2) are responsible for all data transfers between the register files and the memory. The data address driven by the .D units allows data addresses generated from one register file to be used to load or store data to or from the other register file. The 'C67x CPU supports a variety of indirect-addressing modes using either linear- or circular-addressing modes with 5- or 15-bit offsets. All instructions are conditional, and most can access any one of the 32 registers. Some registers, however, are singled out to support specific addressing or to hold the condition for conditional instructions (if the condition is not automatically "true"). The two .M functional units are dedicated for multiplies. The two .S and .L functional units perform a general set of arithmetic, logical, and branch functions with results available every clock cycle.

The processing flow begins when a 256-bit-wide instruction fetch packet is fetched from a program memory. The 32-bit instructions destined for the individual functional units are "linked" together by "1" bits in the least significant bit (LSB) position of the instructions. The instructions that are "chained" together for simultaneous execution (up to eight in total) compose an execute packet. A "0" in the LSB of an instruction breaks the chain, effectively placing the instructions that follow it in the next execute packet. If an execute packet crosses the fetch-packet boundary (256 bits wide), the assembler places it in the next fetch packet, while the remainder of the current fetch packet is padded with NOP instructions. The number of execute packets within a fetch packet can vary from one to eight. Execute packets are dispatched to their respective functional units at the rate of one per clock cycle and the next 256-bit fetch packet is not fetched until all the execute packets from the current fetch packet have been dispatched. After decoding, the instructions simultaneously drive all active functional units for a maximum execution rate of eight instructions every clock cycle. While most results are stored in 32-bit registers, they can be subsequently moved to memory as bytes or half-words as well. All load and store instructions are byte, half-word, or word addressable.

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(1) These functional units execute floating-point instructions.

Figure 1. SMJ320C67x CPU Data Paths



Signal Groups Description

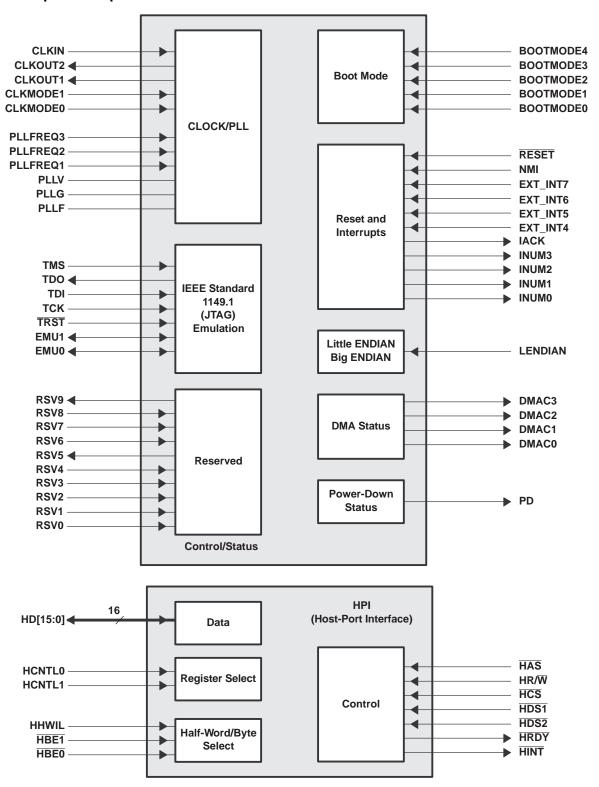


Figure 2. CPU and Peripheral Signals



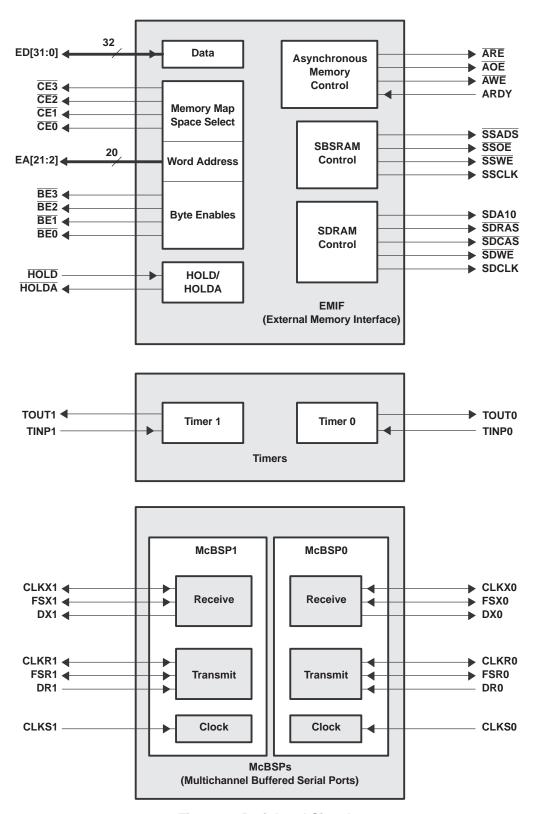


Figure 3. Peripheral Signals



Signal Descriptions

			Signal Descriptions
SIGN	AL	TYPE ⁽¹⁾	DESCRIPTION
NAME	NO.	1111 = 11	DESCRIPTION
			CLOCK/PLL
CLKIN	A14	1	Clock Input
CLKOUT1	Y6	0	Clock output at full device speed
CLKOUT2	V9	0	Clock output at half of device speed
CLKMODE1	B17		Clock mode select
CLKMODE0	C17	I	 Selects whether the output clock frequency = input clock freq x4 or x1
PLLFREQ3	C13		PLL frequency range (3, 2, and 1)
PLLFREQ2	G11	1	 The target range for CLKOUT1 frequency is determined by the
PLLFREQ1	F11		3-bit value of the PLLFREQ pins.
PLLV ⁽²⁾	D12	A ⁽³⁾	PLL analog VCC connection for the low-pass filter
PLLG ⁽²⁾	G10	A ⁽³⁾	PLL analog GND connection for the low-pass filter
PLLF	C12	A ⁽³⁾	PLL low-pass filter connection to external components and a bypass capacitor
			JTAG EMULATION
TMS	K19	I	JTAG test port mode select (features an internal pull-up)
TDO	R12	O/Z	JTAG test port data out
TDI	R13	I	JTAG test port data in (features an internal pull-up)
TCK	M20	I	JTAG test port clock
TRST	N18	I	JTAG test port reset (features an internal pull-down)
EMU1	R20	I/O/Z	Emulation pin 1, pullup with a dedicated 20-kΩ resistor (4)
EMU0	T18	I/O/Z	Emulation pin 0, pullup with a dedicated 20-kΩ resistor (4)
		1	RESET AND INTERRUPTS
RESET	J20	I	Device reset
NMI	K21	I	Nonmaskable interrupt • Edge driven (rising edge)
EXT_INT7	R16		
EXT_INT6	P20		External interrupts
EXT_INT5	R15	'	Edge driven (rising edge)
EXT_INT4	R18		
IACK	R11	0	Interrupt acknowledge for all active interrupts serviced by the CPU
INUM3	T19		Active interrupt identification number
INUM2	T20		 Valid during IACK for all active interrupts (not just external)
INUM1	T14	0	 Encoding order follows the interrupt service fetch packet
INUM0	T16		ordering.
		1	LITTLE ENDIAN/BIG ENDIAN
LENDIAN	G20	I	If high, selects little-endian byte/half-word addressing order within a word. If low, selects big-endian addressing.
			POWER-DOWN STATUS
PD	D19	0	Power-down mode 2 or 3 (active if high)

⁽¹⁾ I = Input, O = Output, Z = High impedance, S = Supply voltage, GND = Ground

⁽²⁾ PLLV and PLLG signals are not part of external voltage supply or ground. See the CLOCK/PLL documentation for information on how to connect those pins.

 ⁽³⁾ A = Analog signal (PLL filter)
 (4) For emulation and normal operation, pull up EMU1 and EMU0 with a dedicated 20-kΩ resistor. For boundary scan, pull down EMU1 and EMU0 with a dedicated 20-k Ω resistor.

Signal Descriptions (continued)

SIGN	IAL	10	
NAME	NO.	TYPE ⁽¹⁾	DESCRIPTION
			HOST-PORT INTERFACE (HPI)
HINT	H2	O/Z	Host interrupt (from DSP to host)
HCNTL1	J6	I	Host control – selects between control, address or data registers
HCNTL0	H6	I	Host control – selects between control, address or data registers
HHWIL	E4	l	Host halfword select – first or second halfword (not necessarily high or low order)
HBE1	G6	ļ	Host byte select within word or half-word
HBE0	F6	I	Host byte select within word or half-word
HR/W	D4	I	Host read or write select
HD15	D11		
HD14	B11		
HD13	A11		
HD12	G9		
HD11	D10		
HD10	A10		
HD9	C10		
HD8	В9	I/O/Z	Heat part data (used for transfer of data, address, and control)
HD7	F9	1/0/2	Host-port data (used for transfer of data, address and control)
HD6	C9		
HD5	A9		
HD4	B8		
HD3	D9		
HD2	D8		
HD1	В7		
HD0	C7		
HAS	L6	I	Host address strobe
HCS	C5	I	Host chip select
HDS1	C4	I	Host data strobe 1
HDS2	K6	I	Host data strobe 2
HRDY	НЗ	0	Host ready (from DSP to host)
			BOOT MODE
BOOTMODE4	B16		
BOOTMODE3	G14		
BOOTMODE2	F15	I	Boot mode
BOOTMODE1	C18		
BOOTMODE0	D17		<u> </u>

Product Folder Links: SMJ320C6701-SP



Signal Descriptions (continued)

2:0	SIGNAL (a)			
		TYPE(1)	DESCRIPTION	
NAME	NO.			
		1	_ SIGNALS COMMON TO ALL TYPES OF MEMORY	
CE3	Y5	O/Z	Memory space enables	
CE2	V3	O/Z	Enabled by bits 24 and 25 of the word address	
CE1	Т6	O/Z	Only one asserted during any external data access	
CE0	U2	O/Z	, , , , , , , , , , , , , , , , , , ,	
BE3	R8	O/Z	Byte enable control	
BE2	T3	O/Z	Decoded from the two lowest bits of the internal address	
BE1	T2	O/Z	Byte write enables for most types of memory	
BE0	R2	O/Z	Can be directly connected to SDRAM read and write mask signal (SDQM)	
		II.	EMIF - ADDRESS	
EA21	L4			
EA20	L3			
EA19	J2			
EA18	J1			
EA17	K1			
EA16	K2			
EA15	L2			
EA14	L1			
EA13	M1			
EA12	M2	1		
EA11	M6	O/Z	External address (word address)	
EA10	N4			
EA9	N1			
EA8	N2	1		
EA7	N6	1		
EA6	P4			
EA5	P3			
EA4	P2			
EA3	P1	1		
EA2	P6			
		1		

S	SIGNAL		
NAME	NO.	TYPE ⁽¹⁾	DESCRIPTION
			EMIF - DATA
ED31	U18		
ED30	U20		
ED29	T15		
ED28	V18		
ED27	V17		
ED26	V16		
ED25	T12		
ED24	W17		
ED23	T13		
ED22	Y17		
ED21	T11		
ED20	Y16		
ED19	W15		
ED18	V14		
ED17	Y15		
ED16	R9	I/O/Z	External data
ED15	Y14	1/0/2	External data
ED14	V13		
ED13	AA13		
ED12	T10		
ED11	Y13		
ED10	W12		
ED9	Y12		
ED8	Y11		
ED7	V10		
ED6	AA10		
ED5	Y10		
ED4	W10		
ED3	Y9		
ED2	AA9		
ED1	Y8		
ED0	W9		
	ı		ASYNCHRONOUS MEMORY CONTROL
ARE	R7	O/Z	Asynchronous memory read enable
AOE	T7	O/Z	Asynchronous memory output enable
AWE	V5	O/Z	Asynchronous memory write enable
ARDY	R4	I	Asynchronous memory ready input



Signal Descriptions (continued)

SIGNAL (a)			
		TYPE ⁽¹⁾	DESCRIPTION
NAME	NO.	EMIF S	SYNCHRONOUS BURST SRAM CONTROL
CCADC	\/0		
SSADS	V8	O/Z	SBSRAM address strobe
SSOE	W7	O/Z	SBSRAM output enable
SSWE	Y7	O/Z	SBSRAM write enable
SSCLK	AA8	O/Z	SBSRAM clock
			F - SYNCHRONOUS DRAM CONTROL
SDA10	V7	O/Z	SDRAM address 10 (separate for deactivate command)
SDRAS	V6	O/Z	SDRAM row address strobe
SDCAS	W5	O/Z	SDRAM column address strobe
SDWE	Т8	O/Z	SDRAM write enable
SDCLK	Т9	O/Z	SDRAM clock
			EMIF - BUS ARBITRATION
HOLD	R6	I	Hold request from the host
HOLDA	B15	0	Hold request acknowledge to the host
			TIMERS
TOUT1	G2	O/Z	Timer 1 or general-purpose output
TINP1	K3	1	Timer 1 or general-purpose input
TOUT0	M18	O/Z	Timer 0 or general-purpose output
TINP0	J18	1	Timer 0 or general-purpose input
			DMA ACTION COMPLETE
DMAC3	E18		
DMAC2	F19		
DMAC1	E20	0	DMA action complete
DMAC0	G16		
		MULTICHA	NNEL BUFFERED SERIAL PORT 1 (McBSP1)
CLKS1	F4	I	External clock source (as opposed to internal)
CLKR1	H4	I/O/Z	Receive clock
CLKX1	J4	I/O/Z	Transmit clock
DR1	E2	1	Receive data
DX1	G4	O/Z	Transmit data
FSR1	F3	I/O/Z	Receive frame sync
FSX1	F2	1/O/Z	Transmit frame sync
1 3/1	ГД	1/0/2	Hansilit hame symb

SIGN	NAL				
NAME	NO.	TYPE ⁽¹⁾	DESCRIPTION		
	MULTICHANNEL BUFFERED SERIAL PORT 0 (McBSP0)				
CLKS0	K18	ı	Extended clock source (as opposed to internal)		
CLKR0	L21	I/O/Z	Receive clock		
CLKX0	K20	I/O/Z	Transmit clock		
DR0	J21	I	Receive data		
DX0	M21	O/Z	Transmit data		
FSR0	P16	I/O/Z	Receive frame sync		
FSX0	N16	I/O/Z	Transmit frame sync		
			RESERVED FOR TEST		
RSV0	N21	I	Reserved for testing, pullup with a dedicated 20-kΩ resistor		
RSV1	K16	1	Reserved for testing, pullup with a dedicated 20-k Ω resistor		
RSV2	B13	I	Reserved for testing, pullup with a dedicated 20-k Ω resistor		
RSV3	B14	I	Reserved for testing, pullup with a dedicated 20-k Ω resistor		
RSV4	F13	1	Reserved for testing, $pulldown$ with a dedicated 20-k Ω resistor		
RSV5	C15	0	Reserved (leave unconnected, do not connect to power or ground)		
RSV6	F7	1	Reserved for testing, pullup with a dedicated 20-k Ω resistor		
RSV7	D7	1	Reserved for testing, pullup with a dedicated 20-k Ω resistor		
RSV8	B5	1	Reserved for testing, pullup with a dedicated 20-k Ω resistor		
RSV9	F16	0	Reserved (leave unconnected, do not connect to power or ground)		
	C14				
	C8				
	E19				
	E3				
	H11				
	H13				
	H9				
	J10				
	J12				
	J14				
DV_DD	J19	S	3.3-V supply voltage		
	J3				
	J8				
	K11				
	K13				
	K15				
	K7				
	K9				
	L10				
	L12				
	L14				



SIGNA	.L	(1)	
NAME	NO.	TYPE ⁽¹⁾	DESCRIPTION
		SUI	PPLY VOLTAGE PINS (CONTINUED)
	L8		
	M11		
	M13		
	M15		
	M7		
	M9		
	N10		
	N12		
	N14		
DV_DD	N19	S	3.3-V supply voltage
	N3		
	N8		
	P11		
	P13		
	P9		
	U19 U3	-	
	W14		
	W8		
	A12		
	A13		
	B10		
	B12		
	B6		
	D15		
	D16		
	F10		
	F14		
01/	F8	0	4.0.V symply yellong
CV _{DD}	G13	S	1.9-V supply voltage
	G7		
	G8		
	K4		
	M3		
	M4		
	A3		
	A5		
	A7		
	A16		



SIGNA	L		
NAME	NO.	TYPE ⁽¹⁾	DESCRIPTION
		SUI	PPLY VOLTAGE PINS (CONTINUED)
	A18		
	AA4		
	AA6		
	AA15		
	AA17		
	AA19		
	B2		
	B4		
	B19		
	C1		
	C3		
	C20		
	D2		
	D21		
	E1		
	E6		
CV _{DD}	E8	S	1.9-V supply voltage
OADD	E10		1.3 V Supply Voltage
	E12		
	E14		
	E16		
	F5		
	F17		
	F21		
	G1		
	H5		
	H17		
	K5		
	K17		
	M5		
	M17		
	P5		
	P17		
	R21		



Signal Descriptions (continued)

SIG	NAL		mai Descriptions (continued)
NAME	NO.	TYPE ⁽¹⁾	DESCRIPTION
		SUF	PPLY VOLTAGE PINS (CONTINUED)
	T1		
	T5		
	T17		
	U6		
	U8		
	U10		
	U12		
	U14		
	U16		
	U21		
	V1		
	V20		
	W2		
	W19		
	W21		
	Y3		
	Y18		
	Y20		
CV _{DD}	AA11	S	1.9-V supply voltage
	AA12		
	F20		
	G18		
	H16		
	H18		
	L18		
	L19		
	L20		
	N20		
	P18		
	P19		
	R10		
	R14	-	
	U4 V11		
	V11 V12		
	V12 V15		
	W13		

SIGNA	AL.		mai Descriptions (continued)
NAME	NO.	TYPE ⁽¹⁾	DESCRIPTION
		1	GROUND PINS
	C11		
	C16		
	C6		
	D5		
	G3		
	H10		
	H12		
	H14		
	H7		
	H8		
	J11		
	J13		
	J7		
	J9		
	K8		
	L7	_	
	L9		
	M8	OND	
V	N7		Crawad
V _{SS}	R3	GND	Ground
	A4 A6		
	A8		
	A15		
	A17		
	A19		
	AA3		
	AA5		
	AA7		
	AA14		
	AA16		
	AA18		
	В3		
	B18		
	B20		
	C2		
	C19		
	C21		
	D1		



SIC	GNAL		mai Descriptions (continued)
NAME	NO.	TYPE ⁽¹⁾	DESCRIPTION
			GROUND PINS (CONTINUED)
	D20		
	E5		
	E7		
	E9		
	E11		
	E13		
	E15		
	E17		
	E21		
	F1		
	G5		
	G17		
	G21		
	H1		
	J5		
	J17		
	L5		
V _{SS}	L17	GND	Ground pins
	N5		
	N17		
	P21		
	R1		
	R5		
	R17		
	T21		
	U1		
	U5		
	U7		
	U9 U11		
	U13		
	U15		
	U17		
	V2		
	V21		
	٧∠١		

SIG	SNAL		
NAME	NO.	TYPE ⁽¹⁾	DESCRIPTION
			GROUND PINS (CONTINUED)
	W1		
	W3		
	W20		
	Y2		
	Y4		
	Y19		
	F18		
	G19		
	H15		
	J15		
	J16		
	K10		
	K12		
	K14		
	L11		
	L13		
	L15		
V_{SS}	M10	GND	Ground pins
	M12		
	M14		
	N11		
	N13		
	N15		
	N9		
	P10		
	P12		
	P14		
	P15		
	P7		
	P8		
	R19		
	T4		
	W11		
	W16		
	W6		



SIGNA	L	TYPE ⁽¹⁾	DESCRIPTION
NAME	NO.	TTPE	DESCRIPTION
		F	REMAINING UNCONNECTED PINS
	D13		
	D14		
	D18		
	D3		
	D6		
	F12		
	G12		
	G15		
NC	H19		Unconnected pins
INC	H20		Onconnected pins
	H21		
	L16		
	M16		
	M19		
	V19		
	V4		
	W18		
	W4		

Development Support

Texas Instruments (TI) offers an extensive line of development tools for the 'C6x generation of DSPs, including tools to evaluate the performance of the processors, generate code, develop algorithm implementations, and fully integrate and debug software and hardware modules.

The following products support development of 'C6x-based applications:

Software-development tools

- Assembly optimizer
- Assembler/Linker
- Simulator
- Optimizing ANSI C compiler
- Application algorithms
- C/Assembly debugger and code profiler

Hardware-development tools

- Extended development system (XDS™) emulator (supports 'C6x multiprocessor system debug)
- EVM (Evaluation Module)

The *TMS320 DSP Development Support Reference Guide* (SPRU011) contains information about development-support products for all TMS320 family member devices, including documentation. See this document for further information on TMS320 documentation or any TMS320 support products from Texas Instruments. An additional document, the *TMS320 Third-Party Support Reference Guide* (SPRU052), contains information about TMS320-related products from other companies in the industry. To receive TMS320 literature, contact the Literature Response Center at 800/477-8924.

See Table 2 for a complete listing of development-support tools for the 'C6x. For information on pricing and availability, contact the nearest TI field sales office or authorized distributor.

Table 2. SMJ320C6x Development-Support Tools

DEVELOPMENT TOOL	PLATFORM	PART NUMBER
,	Software	
Ada 95 Compiler ⁽¹⁾	Sun Solaris 2.3 ^{™ (2)}	AD0345AS8500RF – Single user AD0345BS8500RF – Multi user
C Compiler/Assembler/Linker/Assembly Optimizer	Win32™	TMDX3246855-07
C Compiler/Assembler/Linker/Assembly Optimizer	SPARC™ Solaris™	TMDX3246555-07
Simulator	Win32	TMDS3246851-07
Simulator	SPARC Solaris	TMDS3246551-07
XDS510™ Debugger/Emulation Software	Win32, Windows NT™	TMDX324016X-07
	Hardware	
XDS510 Emulator ⁽³⁾	PC	TMDS00510
XDS510WS™ Emulator ⁽⁴⁾	SCSI	TMDS00510WS
	Software/Hardware	
EVM Evaluation Kit	PC/Win95/Windows NT	TMDX3260A6201
EVM Evaluation Kit (including TMDX3246855-07)	PC/Win95/Windows NT	TMDX326006201

- (1) Contact IRVINE Compiler Corporation (949) 250-1366 to order
- (2) NT support estimated availability 1Q00
- (3) Includes XDS510 board and JTAG emulation cable. TMDX324016X-07 C-source Debugger/Emulation software is not included.
- (4) Includes XDS510WS box, SCSI cable, power supply, and JTAG emulation cable.

Product Folder Links: SMJ320C6701-SP



Device and Development-Support Tool Nomenclature

To designate the stages in the product-development cycle, TI assigns prefixes to the part numbers of all SMJ320 devices and support tools. Each SMJ320 member has one of three prefixes: SMX, SM, or SMJ. Texas Instruments recommends two of three possible prefix designators for support tools: TMDX and TMDS. These prefixes represent evolutionary stages of product development from engineering prototypes (SMX/TMDX) through fully qualified production devices/tools (SMJ/TMDS).

Device development evolutionary flow:

SMX Experimental device that is not necessarily representative of the final device's electrical

specifications

SM Final silicon die that conforms to the device's electrical specifications but has not completed

quality and reliability verification

SMJ Fully qualified production device processed to MIL-PRF-38535

Support tool development evolutionary flow:

Development-support product that has not yet completed Texas Instruments internal **TMDX**

qualification testing.

TMDS Fully qualified development-support product

SMX devices and TMDX development-support tools are shipped against the following disclaimer:

"Developmental product is intended for internal evaluation purposes."

SMJ devices and TMDS development-support tools have been characterized fully, and the quality and reliability of the device have been demonstrated fully. TI's standard warranty applies.

Predictions show that prototype devices (SMX or SM) have a greater failure rate than the standard production devices. Texas Instruments recommends that these devices not be used in any production system because their expected end-use failure rate still is undefined. Only qualified production devices are to be used.

TI device nomenclature also includes a suffix with the device family name. This suffix indicates the package type (for example, GLP), the temperature range, and the device speed range in megahertz (for example, 14 is 140 MHz). Figure 4 provides a legend for reading the complete device name for any SMJ320 family member.



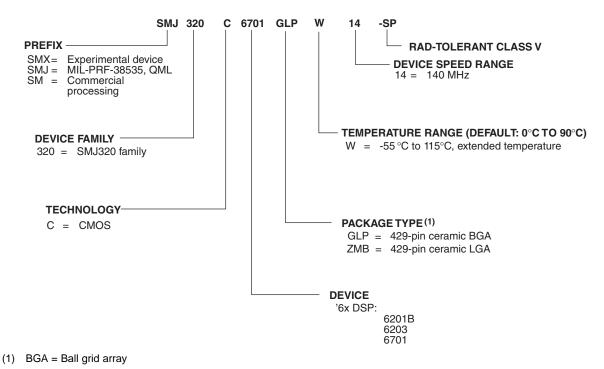


Figure 4. SMJ320 Device Nomenclature (Including SMJ320C6701-SP)

Documentation Support

Extensive documentation supports all SMJ320 family generations of devices from product announcement through applications development. The types of documentation available include: data sheets, such as this document, with design specifications; complete user's reference guides for all devices; technical briefs; development-support tools; and hardware and software applications. The following is a brief, descriptive list of support documentation specific to the 'C6x devices:

The *TMS320C6000 CPU* and *Instruction Set Reference Guide* (literature number SPRU189) describes the 'C6000 CPU architecture, instruction set, pipeline, and associated interrupts.

The *TMS320C6000 Peripherals Reference Guide* (literature number SPRU190) describes the functionality of the peripherals available on 'C6x devices, such as the external memory interface (EMIF), host-port interface (HPI), multichannel buffered serial ports (McBSPs), direct-memory-access (DMA), enhanced direct-memory-access (EDMA) controller, expansion bus (XB), clocking and phase-locked loop (PLL); and power-down modes. This guide also includes information on internal data and program memories.

The *TMS320C6000 Programmer's Guide* (literature number SPRU198) describes ways to optimize C and assembly code for 'C6x devices and includes application program examples.

The TMS320C6x C Source Debugger User's Guide (literature number SPRU188) describes how to invoke the 'C6x simulator and emulator versions of the C source debugger interface and discusses various aspects of the debugger, including: command entry, code execution, data management, breakpoints, profiling, and analysis.

The TMS320C6x Peripheral Support Library Programmer's Reference (literature number SPRU273) describes the contents of the 'C6x peripheral support library of functions and macros. It lists functions and macros both by header file and alphabetically, provides a complete description of each, and gives code examples to show how they are used.

TMS320C6000 Assembly Language Tools User's Guide (literature number SPRU186) describes the assembly language tools (assembler, linker, and other tools used to develop assembly language code), assembler directives, macros, common object file format, and symbolic debugging directives for the 'C6000 generation of devices.

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The *TMS320C6x Evaluation Module Reference Guide* (literature number SPRU269) provides instructions for installing and operating the 'C6x evaluation module. It also includes support software documentation, application programming interfaces, and technical reference material.

TMS320C6000 DSP/BIOS User's Guide (literature number SPRU303) describes how to use DSP/BIOS tools and APIs to analyze embedded real-time DSP applications.

Code Composer User's Guide (literature number SPRU296) explains how to use the Code Composer development environment to build and debug embedded real-time DSP applications.

Code Composer Studio Tutorial (literature number SPRU301) introduces the Code Composer Studio integrated development environment and software tools.

The *TMS320C6000 Technical Brief* (literature number SPRU197) gives an introduction to the 'C62x/C67x devices, associated development tools, and third-party support.

A series of DSP textbooks is published by Prentice-Hall and John Wiley & Sons to support DSP research and education. The TMS320 newsletter, *Details on Signal Processing*, is published quarterly and distributed to update SMJ320 customers on product information. The TMS320 DSP bulletin board service (BBS) provides access to information pertaining to the SMJ320 family, including documentation, source code, and object code for many DSP algorithms and utilities. The BBS can be reached at 281/274-2323.

Information regarding TI DSP products is also available on the Worldwide Web at http://www.ti.com uniform resource locator (URL).

Clock PLL

All of the internal 'C67x clocks are generated from a single source through the CLKIN pin. This source clock either drives the PLL, which multiplies the source clock in frequency to generate the internal CPU clock, or bypasses the PLL to become the internal CPU clock.

To use the PLL to generate the CPU clock, the external PLL filter circuit must be properly designed. Table 3, Table 4, and Figure 5 show the external PLL circuitry for either x1 (PLL bypass) or x4 PLL multiply modes. Table 3 and Figure 6 show the external PLL circuitry for a system with ONLY x1 (PLL bypass) mode.

To minimize the clock jitter, a single clean power supply should power both the 'C67x device and the external clock oscillator circuit. Noise coupling into PLLF will directly impact PLL clock jitter. The minimum CLKIN rise and fall times should also be observed. For the input clock timing requirements, see the *input and output clocks* electricals section. Guidelines for EMI filter selection are as follows: maximum attenuation frequency = 20–30 MHz, maximum dB attenuation = 45–50 dB, and minimum dB attenuation above 30 MHz = 20 dB.

Table 3. CLKOUT1 Frequency Ranges (1)

PLLFREQ3	PLLFREQ2	PLLFREQ1	CLKOUT1 FREQUENCY RANGE
(C13)	(G11)	(F11)	(MHz)
0	0	0	50-140

⁽¹⁾ Due to overlap of frequency ranges when choosing the PLLFREQ, more than one frequency range can contain the CLKOUT1 frequency. Choose the lowest frequency range that includes the desired frequency. For example, for CLKOUT1 = 133 MHz, choose PLLFREQ value of 000b. PLLFREQ values other than 000b, 001b, and 010b are reserved.

Table 4. 'C6701 PLL Component Selection Table

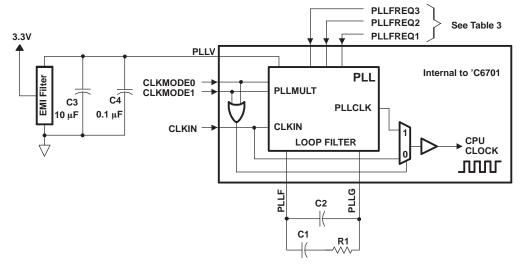
CLKI	MODE	CLKIN RANGE (MHz)	CPU CLOCK FREQUENCY (CLKOUT1) RANGE (MHz)	CLKOUT2 RANGE (MHz)	R1 (W)	C1 (nF)	C2 (pF)	TYPICAL LOCK TIME (µs) ⁽¹⁾
х	4	12.5 – 41.7	50-140	25 – 83.5	60.4	27	560	75

⁽¹⁾ Under some operating conditions, the maximum PLL lock time may vary as much as 150% from the specified typical value. For example, if the typical lock time is specified as 100 μs, the maximum value may be as long as 250 μs.

AVAILABLE MULTIPLY FACTORS							
CLKMODE1	CLKMODE0	PLL MULTIPLY FACTORS	CPU CLOCK FREQUENCY F(CPUCLOCK)				
0	0	x1(BYPASS)	1 x f(CLKIN)				

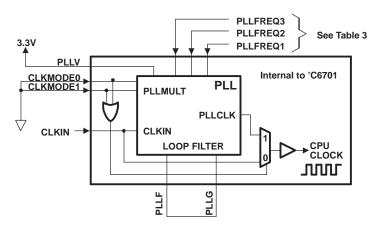
Product Folder Links: SMJ320C6701-SP

AVAILABLE MULTIPLY FACTORS							
CLKMODE1	CLKMODE0	PLL MULTIPLY FACTORS	CPU CLOCK FREQUENCY F(CPUCLOCK)				
0	1	Reserved	Reserved				
1	0	Reserved	Reserved				
1	1	x4	4 x f(CLKIN)				



- (1) Keep the lead length and the number of vias between the PLLF pin, the PLLG pin, and R1, C1, and C2 to a minimum. In addition, place all PLL external components (R1, C1, C2, C3, C4, and the EMI filter) as close to the 'C6000 device as possible. For the best performance, TI recommends that all the PLL external components be on a single side of the board without jumpers, switches, or components other than the ones shown.
- (2) For reduced PLL jitter, maximize the spacing between switching signals and the PLL external components (R1, C1, C2, C3, C4, and the EMI filter).
- (3) The 3.3-V supply for the EMI filter must be from the same 3.3-V power plane supplying the I/O voltage, DV_{DD}.

Figure 5. External PLL Circuitry for Either PLL ×4 Mode or ×1 (Bypass) Mode



- (1) For a system with ONLY PLL x1 (bypass) mode, short the PLLF terminal to the PLLG terminal.
- (2) The 3.3-V supply for the EMI filter must be from the same 3.3-V power plane supplying the I/O voltage, DV_{DD}.

Figure 6. External PLL Circuitry for ×1 (Bypass) Mode Only



Power-Supply Sequencing

TI DSPs do not require specific power sequencing between the core supply and the I/O supply. However, systems should be designed to ensure that neither supply is powered up for extended periods of time if the other supply is below the proper operating voltage.

System-Level Design Considerations

System-level design considerations, such as bus contention, may require supply sequencing to be implemented. In this case, the core supply should be powered up at the same time as, or prior to (and powered down after), the I/O buffers. This is to ensure that the I/O buffers receive valid inputs from the core before the output buffers are powered up, thus, preventing bus contention with other chips on the board.

Power-Supply Design Considerations

For systems using the C6000™ DSP platform of devices, the core supply may be required to provide in excess of 2 A per DSP until the I/O supply is powered up. This extra current condition is a result of uninitialized logic within the DSP(s) and is corrected once the CPU sees an internal clock pulse. With the PLL enabled, as the I/O supply is powered on, a clock pulse is produced stopping the extra current draw from the supply. With the PLL disabled, an external clock pulse may be required to stop this extra current draw. A normal current state returns once the I/O power supply is turned on and the CPU sees a clock pulse. Decreasing the amount of time between the core supply power up and the I/O supply power up can minimize the effects of this current draw.

A dual-power supply with simultaneous sequencing, such as available with TPS563xx controllers or PT69xx plugin power modules, can be used to eliminate the delay between core and I/O power up [see the Using the TPS56300 to Power DSPs application report (literature number SLVA088)]. A Schottky diode can also be used to tie the core rail to the I/O rail, effectively pulling up the I/O power supply to a level that can help initialize the logic within the DSP.

Core and I/O supply voltage regulators should be located close to the DSP (or DSP array) to minimize inductance and resistance in the power delivery path. Additionally, when designing for high-performance applications utilizing the C6000™ platform of DSPs, the PC board should include separate power planes for core, I/O, and ground, all bypassed with high-quality low-ESL/ESR capacitors.

Absolute Maximum Ratings(1)

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
CV_{DD}	Supply voltage range (2)		-0.3	2.3	V
DV_DD	Supply voltage range (2)			4	V
	Input voltage range			4	V
	Output voltage range		-0.3	4	V
_		S-suffix device	-40	90	°C
IC	Operating case temperature range	W-suffix device	-55	115	٠.
T _{stg}	Storage temperature range	,	– 55	150	°C

⁽¹⁾ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

Recommended Operating Conditions

				MIN	NOM	MAX	UNIT	
CV_{DD}	Supply voltage			1.81	1.9	1.99	V	
DV_DD	Supply voltage			3.14	3.3	3.46	V	
V_{SS}	Supply ground			0	0	0	V	
V_{IH}	High-level input voltage			2			V	
V_{IL}	Low-level input voltage					0.8	V	
I _{OH}	High-level output current					-12	mA	
I _{OL}	Low-level output current					12	mA	
_	Cara tamanantun	S-suffix device		-40		90	°C	
T _C	Case temperature	W-suffix device		- 55		115		

Product Folder Links: SMJ320C6701-SP

⁽²⁾ All voltage values are with respect to VSS.



Electrical Characteristics

over recommended ranges of supply voltage and operating case temperature (unless otherwise noted) (unchanged after 100 kRad)

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
V _{OH}	High-level output voltage	$DV_{DD} = MIN$, $I_{OH} = MAX$	2.4			V
V _{OL}	Low-level output voltage	$DV_{DD} = MIN$, $I_{OL} = MAX$			0.6	V
I _I	Input current ⁽¹⁾	$V_I = V_{SS}$ to DV_{DD}			±10	μΑ
l _{OZ}	Off-state output current	V _O = DV _{DD} or 0 V			±10	μΑ
I _{DD2V}	Supply current, CPU + CPU memory access (2)	CV _{DD} = NOM, CPU clock = 150 MHz		470		mA
I _{DD2V}	Supply current, peripherals (3)	CV _{DD} = NOM, CPU clock = 150 MHz		250		mA
I _{DD3V}	Supply current, I/O pins (4)	DV _{DD} = NOM, CPU clock = 150 MHz		85		mA
Ci	Input capacitance				15 ⁽⁵⁾	pF
Co	Output capacitance				15 ⁽⁵⁾	pF

(1) TMS and TDI are not included due to internal pullups. TRST is not included due to internal pulldown.

(2) Measured with average CPU activity: 50% of time: 8 instructions per cycle, 32-bit DMEM access per cycle

(3) Measured with average peripheral activity:
50% of time: Timers at max rate, McBSPs at E1 rate, and DMA burst transfer between DMEM and SDRAM

50% of time: Timers at max rate, McBSPs at E1 rate, and DMA servicing McBSPs

50% of time: 2 instructions per cycle, 16-bit DMEM access per cycle

(4) Measured with average I/O activity (30-pF load, SDCLK on):

25% of time: Reads from external SDRAM

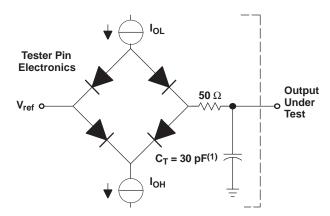
25% of time: Writes to external SDRAM

50% of time: No activity

(5) This parameter is not tested.



PARAMETER MEASUREMENT INFORMATION



(1) Typical distributed load circuit capacitance.

Signal-Transition Levels

All input and output timing parameters are referenced to 1.5 V for both "0" and "1" logic levels.



Figure 7. Input and Output Voltage Reference Levels for AC Timing Measurements



INPUT AND OUTPUT CLOCKS

Timing Requirements for CLKIN⁽¹⁾

(see Figure 8)

NO.			CLKMODE =	= x4	CLKMODE = 3	x1	UNIT
NO.			MIN	MAX	MIN	MAX	UNII
1	t _{c(CLKIN)}	Cycle time, CLKIN	28.4		7.1		ns
2	t _{w(CLKINH)}	Pulse duration, CLKIN high	0.4C ⁽²⁾ (3)		0.45C (2) (3)		ns
3	t _{w(CLKINL)}	Pulse duration, CLKIN low	0.4C ⁽²⁾ (3)		0.45C ⁽²⁾ (3)		ns
4	t _{t(CLKIN)}	Transition time, CLKIN		5 ⁽²⁾		0.6 ⁽²⁾	ns

- The reference points for the rise and fall transitions ar measured at 20% and 80%, respectively, of V_{IH} .
- This parameter is not tested.
- C = CLKIN cycle time in ns. For example, when CLKIN frequency is 10 MHz, use C = 100 ns.

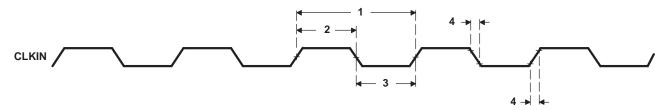


Figure 8. CLKIN Timing

Switching Characteristics for CLKOUT1⁽¹⁾ (2)

(see Figure 9)

(55550	• • •						
NO.	PARAMETER		CLKMO	DE = x4	CLKMO	UNIT	
NO.		PARAMETER	MIN	MAX	MIN	MAX	UNII
1	t _{c(CKO1)}	Cycle time, CLKOUT1	P - 0.7 ⁽³⁾	P + 0.7 ⁽³⁾	$P - 0.7^{(3)}$	P + 0.7 ⁽³⁾	ns
2	t _{w(CKO1H)}	Pulse duration, CLKOUT1 high	$(P/2) - 0.5^{(3)}$	$(P/2) + 0.5^{(3)}$	$PH - 0.5^{(3)}$	PH + 0.5 ⁽³⁾	ns
3	t _{w(CKO1L)}	Pulse duration, CLKOUT1 low	$(P/2) - 0.5^{(3)}$	$(P/2) + 0.5^{(3)}$	$PL - 0.5^{(3)}$	PL + 0.5 ⁽³⁾	ns
4	t _{t(CKO1)}	Transition time, CLKOUT1		0.6 ⁽³⁾		0.6 ⁽³⁾	ns

- P = 1/CPU clock frequency in nanoseconds (ns).
 PH is the high period of CLKIN in ns and PL is the low period of CLKIN in ns.
- This parameter is not tested.

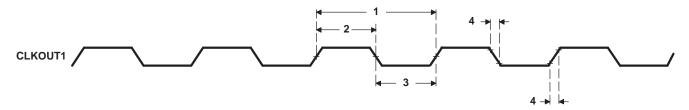


Figure 9. CLKOUT1 Timing

Switching Characteristics for CLKOUT2⁽¹⁾

(see Figure 10)

NO.		PARAMETER	MIN	MAX	UNIT
1	t _{c(CKO2)}	Cycle time, CLKOUT2	2P - 0.7 ⁽²⁾	2P + 0.7 ⁽²⁾	ns
2	t _{w(CKO2H)}	Pulse duration, CLKOUT2 high	P - 0.7 ⁽²⁾	P + 0.7 ⁽²⁾	ns
3	t _{w(CKO2L)}	Pulse duration, CLKOUT2 low	P - 0.7 ⁽²⁾	P + 0.7 ⁽²⁾	ns
4	t _{t(CKO2)}	Transition time, CLKOUT2		0.6(2)	ns

- (1) P = 1/CPU clock frequency in ns.
- (2) This parameter is not tested.

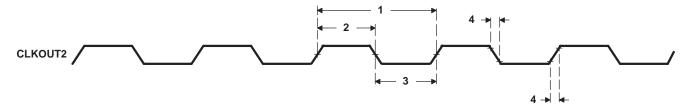


Figure 10. CLKOUT2 Timing

SDCLK, SSCLK Timing Parameter

SDCLK timing parameters are the same as CLKOUT2 parameters.

SSCLK timing parameters are the same as CLKOUT1 or CLKOUT2 parameters, depending on SSCLK configuration.

Switching Characteristics for the Relation of SSCLK, SDCLK, and CLKOUT2 to CLKOUT1

(see Figure 11)

NO.		PARAMETER	MIN	MAX	UNIT
1	t _{d(CKO1-SSCLK)}	Delay time, CLKOUT1 edge to SSCLK edge	-0.8	3.4	ns
2	t _{d(CKO1-SSCLK1/2)}	Delay time, CLKOUT1 edge to SSCLK edge (1/2 clock rate)	-1	3	ns
3	t _{d(CKO1-CKO2)}	Delay time, CLKOUT1 edge to CLKOUT2 edge	-1.5	2.5	ns
4	t _{d(CKO1-SDCLK)}	Delay time, CLKOUT1 edge to SDCLK edge	-1.5	1.9	ns

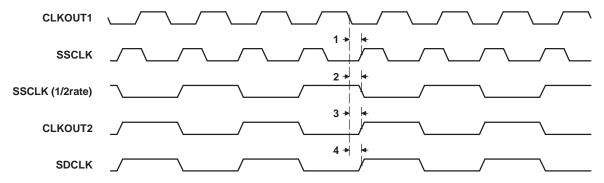


Figure 11. Relation of CLKOUT2, SDCLK, and SSCLK to CLKOUT1



ASYNCHRONOUS MEMORY TIMING

Timing Requirements for Asynchronous Memory Cycles⁽¹⁾

(see Figure 12 and Figure 13)

NO.			MIN	MAX	UNIT
6	t _{su(EDV-CKO1H)}	Setup time, read EDx valid before CLKOUT1 high	4.8		ns
7	t _{h(CKO1H-EDV)}	Hold time, read EDx valid after CLKOUT1 high	1.5		ns
10	t _{su(ARDY-CKO1H)}	Setup time, ARDY valid before CLKOUT1 high	3.5		ns
11	t _h (CKO1H-ARDY)	Hold time, ARDY valid after CLKOUT1 high	1.5		ns

⁽¹⁾ To ensure data setup time, simply program the strobe width wide enough. ARDY is internally synchronized. If ARDY does meet setup or hold time, it may be recognized in the current cycle or the next cycle. Thus, ARDY can be an asynchronous input.

Switching Characteristics for Asynchronous Memory Cycles⁽¹⁾

(see Figure 12 and Figure 13)

NO.		PARAMETER	MIN	MAX	UNIT
1	t _{d(CKO1H} -CEV)	Delay time, CLKOUT1 high to CEx valid	-1	4.5	ns
2	t _{d(CKO1H} BEV)	Delay time, CLKOUT1 high to BEx valid		4.5	ns
3	t _{d(CKO1H} BEIV)	Delay time, CLKOUT1 high to BEx invalid	-1		ns
4	t _{d(CKO1H-EAV)}	Delay time, CLKOUT1 high to EAx valid		4.5	ns
5	t _{d(CKO1H-EAIV)}	Delay time, CLKOUT1 high to EAx invalid	-1		ns
8	t _{d(CKO1H-AOEV)}	Delay time, CLKOUT1 high to AOE valid	-1	4.5	ns
9	t _{d(CKO1H-AREV)}	Delay time, CLKOUT1 high to ARE valid	-1	4.5	ns
12	t _{d(CKO1H-EDV)}	Delay time, CLKOUT1 high to EDx valid		4.5	ns
13	t _{d(CKO1H} EDIV)	Delay time, CLKOUT1 high to EDx invalid	-1		ns
14	t _{d(CKO1H} -AWEV)	Delay time, CLKOUT1 high to AWE valid	-1	4.5	ns

(1) The minimum delay is also the minimum output hold after CLKOUT1 high.

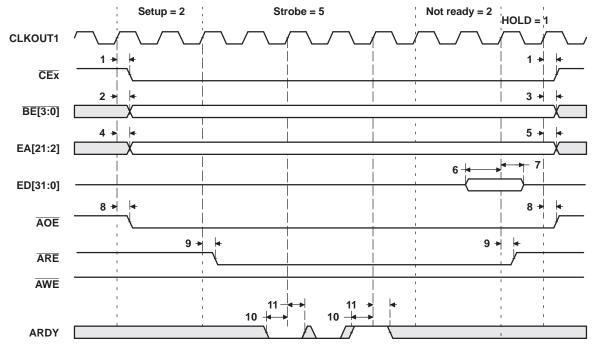


Figure 12. Asynchronous Memory Read Timing



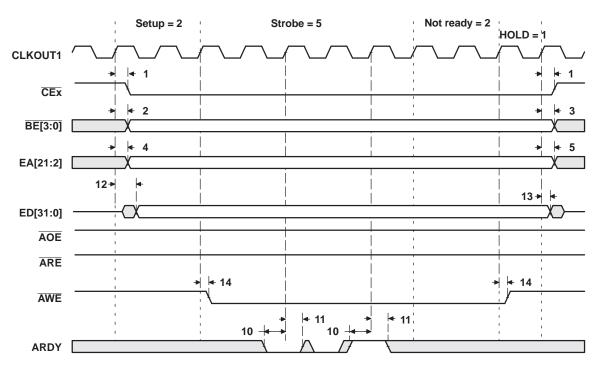


Figure 13. Aysnchronous Memory Write Timing



SYNCHRONOUS-BURST MEMORY TIMING

Timing Requirements for Synchronous-Burst SRAM Cycles (Full-Rate SSCLK)

(see Figure 14)

NO.			MIN	MAX	UNIT
7	t _{su(EDV} -SSCLKH)	Setup time, read EDx valid before SSCLK high	2.6		ns
8	t _h (SSCLKH-EDV)	Hold time, read EDx valid after SSCLK high	1.5		ns

Switching Characteristics for Synchronous-burst SRAM Cycles⁽¹⁾ (Full-Rate SSCLK)

(see Figure 14 and Figure 15)

NO.		PARAMETER	MIN MAX	UNIT
1	t _{osu(CEV-SSCLKH)}	Output setup time, CEx valid before SSCLK high	0.5P - 1.5	ns
2	toh(SSCLKH-CEV)	Output hold time, CEx valid after SSCLK high	0.5P - 2.5	ns
3	t _{osu(BEV-SSCLKH)}	Output setup time, BEx valid before SSCLK high	0.5P - 1.6	ns
4	toh(SSCLKH-BEIV)	Output hold time, BEx invalid after SSCLK high	0.5P - 2.5	ns
5	t _{osu(EAV-SSCLKH)}	Output setup time, EAx valid before SSCLK high	0.5P - 1.7	ns
6	toh(SSCLKH-EAIV)	Output hold time, EAx invalid after SSCLK high	0.5P - 2.5	ns
9	t _{osu(ADSV} -SSCLKH)	Output setup time, SSADS valid before SSCLK high	0.5P - 1.5	ns
10	toh(SSCLKH-ADSV)	Output hold time, SSADS valid after SSCLK high	0.5P - 2.5	ns
11	t _{osu(OEV} -SSCLKH)	Output setup time, SSOE valid before SSCLK high	0.5P - 1.5	ns
12	t _{oh(SSCLKH-OEV)}	Output hold time, SSOE valid after SSCLK high	0.5P - 2.5	ns
13	t _{osu(EDV-SSCLKH)}	Output setup time, EDx valid before SSCLK high	0.5P - 1.5	ns
14	toh(SSCLKH-EDIV)	Output hold time, EDx invalid after SSCLK high	0.5P - 2.5	ns
15	t _{osu(WEV-SSCLKH)}	Output setup time, SSWE valid before SSCLK high	0.5P - 1.5	ns
16	toh(SSCLKH-WEV)	Output hold time, SSWE valid after SSCLK high	0.5P - 2.5	ns

⁽¹⁾ The effects of internal clock jitter are included at test. There is no need to adjust timing numbers for internal clock jitter. When the PLL is used (CLKMODE x4), P = 1/CPU clock frequency in ns. For example, when running parts at 140 MHz, use P = 7 ns. For CLKMODE x1, 0.5P is defined as PH (pulse duration of CLKIN high) for all output setup times; 0.5P is defined as PL (pulse duration of CLKIN low) for all output hold times.

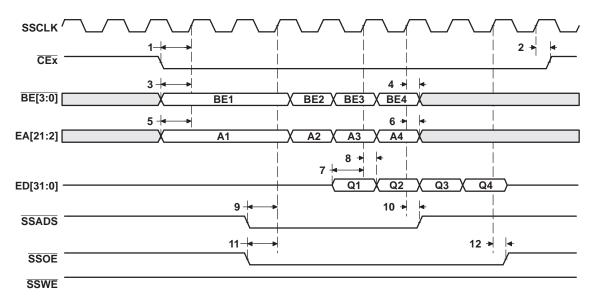


Figure 14. SBSRAM Read Timing (Full-Rate SSCLK)



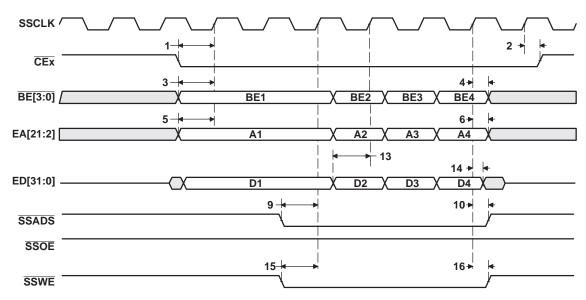


Figure 15. SBSRAM Write Timing (Full-Rate SSCLK)

Timing Requirements for Synchronous-Burst SRAM Cycles (Half-Rate SSCLK)

(seeFigure 16)

NO.			MIN	MAX	UNIT
7	t _{su(EDV} -SSCLKH)	Setup time, read EDx valid before SSCLK high	3.8		ns
8	t _{h(SSCLKH-EDV)}	Hold time, read EDx valid after SSCLK high	1.5		ns

Switching Characteristics for Synchronous-Burst SRAM Cycles⁽¹⁾ (Half-Rate SSCLK)

(see Figure 16 and Figure 17)

NO.		PARAMETER	MIN MAX	UNIT
1	t _{osu(CEV-SSCLKH)}	Output setup time, CEx valid before SSCLK high	1.5P - 5.5	ns
2	t _{oh(SSCLKH-CEV)}	Output hold time, CEx valid after SSCLK high	0.5P - 2.3	ns
3	t _{osu(BEV-SSCLKH)}	Output setup time, BEx valid before SSCLK high	1.5P - 5.5	ns
4	toh(SSCLKH-BEIV)	Output hold time, BEx invalid after SSCLK high	0.5P - 2.3	ns
5	t _{osu(EAV-SSCLKH)}	Output setup time, EAx valid before SSCLK high	1.5P - 5.5	ns
6	toh(SSCLKH-EAIV)	Output hold time, EAx invalid after SSCLK high	0.5P - 2.3	ns
9	t _{osu(ADSV-SSCLKH)}	Output setup time, SSADS valid before SSCLK high	1.5P - 5.5	ns
10	toh(SSCLKH-ADSV)	Output hold time, SSADS valid after SSCLK high	0.5P - 2.3	ns
11	t _{osu(OEV} -SSCLKH)	Output setup time, SSOE valid before SSCLK high	1.5P - 5.5	ns
12	toh(SSCLKH-OEV)	Output hold time, SSOE valid after SSCLK high	0.5P - 2.3	ns
13	t _{osu(EDV-SSCLKH)}	Output setup time, EDx valid before SSCLK high	1.5P - 5.5	ns
14	t _{oh(SSCLKH-EDIV)}	Output hold time, EDx invalid after SSCLK high	0.5P - 2.3	ns
15	t _{osu(WEV-SSCLKH)}	Output setup time, SSWE valid before SSCLK high	1.5P - 5.5	ns
16	t _{oh(SSCLKH-WEV)}	Output hold time, SSWE valid after SSCLK high	0.5P - 2.3	ns

⁽¹⁾ The effects of internal clock jitter are included at test. There is no need to adjust timing numbers for internal clock jitter. When the PLL is used (CLKMODE x4), P = 1/CPU clock frequency in ns. For example, when running parts at 140 MHz, use P = 7 ns. For CLKMODE x1:

^{1.5}P = P + PH, where P = 1/CPU clock frequency, and PH = pulse duration of CLKIN high.

^{0.5}P = PL, where PL = pulse duration of CLKIN low.



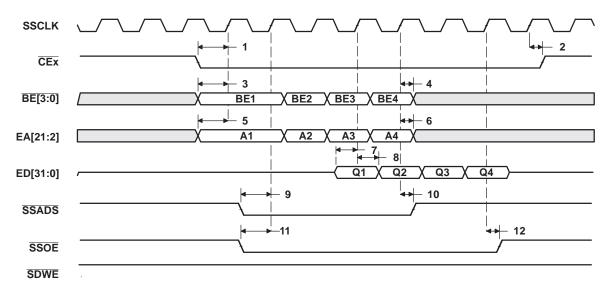


Figure 16. SBSRAM Read Timing (Half-Rate SSCLK)

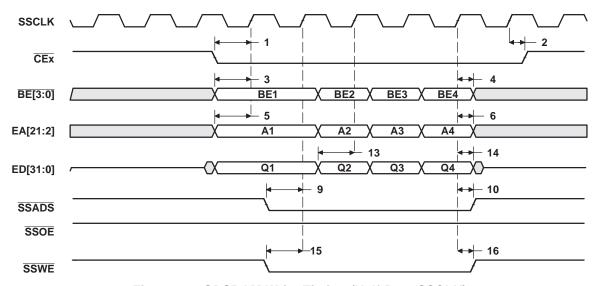


Figure 17. SBSRAM Write Timing (Half-Rate SSCLK)

SYNCHRONOUS DRAM TIMING

Timing Requirements for Synchronous DRAM Cycles

(see Figure 18)

NO.		MIN	MAX	UNIT
7	t _{su(EDV-SDCLKH)} Setup time, read EDx valid before SDCLK high	2		ns
8	t _{h(SDCLKH-EDV)} Hold time, read EDx valid after SDCLK high	3		ns

Switching Characteristics for Synchronous DRAM Cycles⁽¹⁾

(see Figure 18 - Figure 23)

NO.		PARAMETER	MIN MAX	UNIT
1	t _{osu(CEV-SDCLKH)}	Output setup time, CEx valid before SDCLK high	1.5P – 5	ns
2	toh(SDCLKH-CEV)	Output hold time, CEx valid after SDCLK high	0.5P - 1.9	ns
3	t _{osu(BEV-SDCLKH)}	Output setup time, BEx valid before SDCLK high	1.5P – 5	ns
4	toh(SDCLKH-BEIV)	Output hold time, BEx invalid after SDCLK high	0.5P - 1.9	ns
5	t _{osu(EAV-SDCLKH)}	Output setup time, EAx valid before SDCLK high	1.5P – 5	ns
6	t _{oh(SDCLKH-EAIV)}	Output hold time, EAx invalid after SDCLK high	0.5P - 1.9	ns
9	tosu(SDCAS-SDCLKH)	Output setup time, SDCAS valid before SDCLK high	1.5P – 5	ns
10	toh(SDCLKH-SDCAS)	Output hold time, SDCAS valid after SDCLK high	0.5P - 1.9	ns
11	t _{osu(EDV} -SDCLKH)	Output setup time, EDx valid before SDCLK high	1.5P – 5	ns
12	t _{oh(SDCLKH-EDIV)}	Output hold time, EDx invalid after SDCLK high	0.5P - 1.9	ns
13	t _{osu(SDWE-SDCLKH)}	Output setup time, SDWE valid before SDCLK high	1.5P – 5	ns
14	toh(SDCLKH-SDWE)	Output hold time, SDWE valid after SDCLK high	0.5P - 1.9	ns
15	tosu(SDA10V-SDCLKH)	Output setup time, SDA10 valid before SDCLK high	1.5P – 5	ns
16	toh(SDCLKH-SDA10IV)	Output hold time, SDA10 invalid after SDCLK high	0.5P - 1.9	ns
17	t _{osu(SDRAS-SDCLKH)}	Output setup time, SDRAS valid before SDCLK high	1.5P – 5	ns
18	toh(SDCLKH-SDRAS)	Output hold time, SDRAS valid after SDCLK high	0.5P - 1.9	ns

⁽¹⁾ The effects of internal clock jitter are included at test. There is no need to adjust timing numbers for internal clock jitter. When the PLL is used (CLKMODE x4), P = 1/CPU clock frequency in ns. For example, when running parts at 140 MHz, use P = 7 ns. For CLKMODE x1:

^{1.5}P = P + PH, where P = 1/CPU clock frequency, and PH = pulse duration of CLKIN high.

^{0.5}P = PL, where PL = pulse duration of CLKIN low.



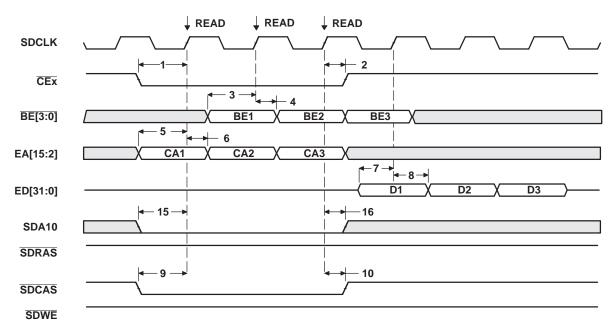


Figure 18. Three SDRAM Read Commands

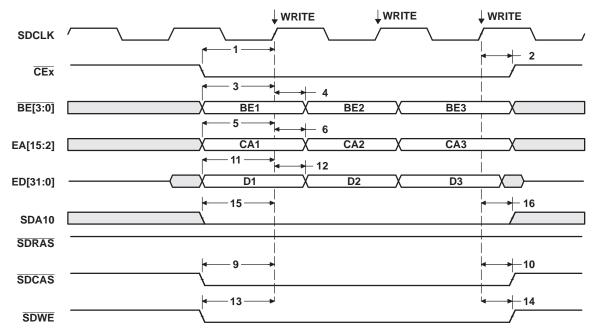


Figure 19. Three SDRAM Write Commands



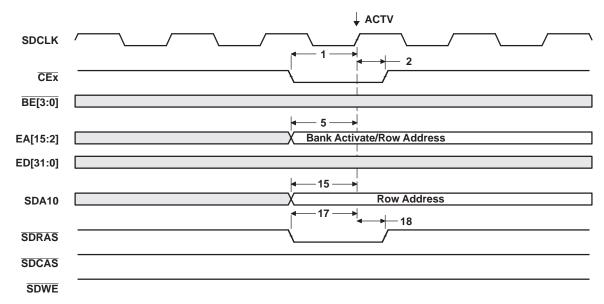


Figure 20. SDRAM ACTV Command

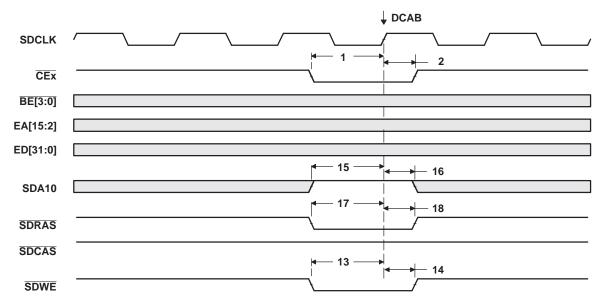


Figure 21. SDRAM DCAB Command



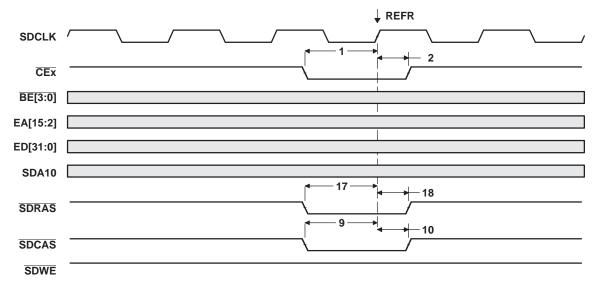


Figure 22. SDRAM REFR Command

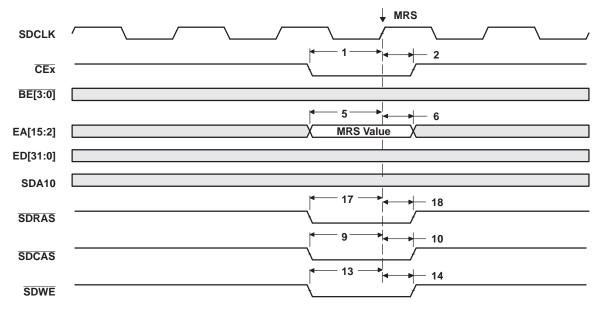


Figure 23. SDRAM MRS Command

HOLD/HOLDA TIMING

Timing Requirements for the Hold/Hold Acknowledge Cycles⁽¹⁾

(see Figure 24)

NO.			MIN	MAX	UNIT
1	t _{su(HOLDH-CKO1H)}	Setup time, HOLD high before CLKOUT1 high	5		ns
2	t _h (CKO1H-HOLDL)	Hold time, HOLD low after CLKOUT1 high	2		ns

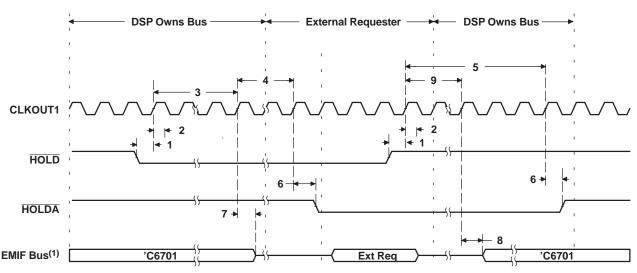
HOLD is synchronized internally. Therefore, if setup and hold times are not met, it will either be recognized in the current cycle or in the next cycle. Thus, HOLD can be an asynchronous input.

Switching Characteristics for the Hold/Hold Acknowledge Cycles⁽¹⁾

(seeFigure 24)

NO.		PARAMETER		MAX	UNIT
3	t _{R(HOLDL-EMHZ)}	Response time, HOLD low to EMIF high impedance	4P		⁽²⁾ ns
4	t _{R(EMHZ-HOLDAL)}	Response time, EMIF high impedance to HOLDA low		2P	ns
5	t _{R(HOLDH-HOLDAH)}	Response time, HOLD high to HOLDA high	4P	7P	ns
6	t _{d(CKO1H} HOLDAL)	Delay time, CLKOUT1 high to HOLDA valid	1	8	ns
7	t _{d(CKO1H-BHZ)}	Delay time, CLKOUT1 high to EMIF Bus high impedance (3)	1 ⁽⁴⁾	8 ⁽⁴⁾	ns
8	t _{d(CKO1H-BLZ)}	Delay time, CLKOUT1 high to EMIF Bus low impedance (3)	1 ⁽⁴⁾	12 ⁽⁴⁾	ns
9	t _{R(HOLDH-BLZ)}	Response time, HOLD high to EMIF Bus low impedance (3)	3P	6P	ns

- P = 1/CPU clock frequency in ns. For example, when running parts at 140 MHz, use P = 7 ns.
- All pending EMIF transactions are allowed to complete before HOLDA is asserted. The worst cases for this is an asynchronous read or write with external ARDY used or a minimum of eight consecutive SDRAM reads or writes when RBTR8 = 1. If no bus transactions are occurring, then the minimum delay time can be achieved. Also, bus hold can be indefinitely delayed by setting the NOHOLD = 1. EMIF Bus consists of CE[3:0], BE[3:0], ED[31:0], EA[21:2], ARE, AOE, AWE, SSADS, SSOE, SSWE, SDA10, SDRAS, SDCAS, and
- SDWE.
- This parameter is not tested.



EMIF bus consists of CE[3:0], BE[3:0], ED[31:0], EA[21:2], ARE, AOE, AWE, SSADS, SSOE, SSWE, SDA10, SDRAS, SDCAS, and SDWE.

Figure 24. HOLD/HOLDA Timing



RESET TIMING

Timing Requirements for Reset

(see Figure 25)

NO.			MIN	MAX	UNIT
1	t _{w(RESET)}	Width of the RESET pulse (PLL stable) ⁽¹⁾	10 ⁽²⁾		CLKOUT 1 cycles
		Width of the RESET pulse (PLL needs to sync up) (3)	250 ⁽²⁾		μs

- 1) This parameter applies to CLKMODE x1 when CLKIN is stable and applies to CLKMODE x4 when CLKIN and PLL are stable.
- 2) This parameter is not tested.
- (3) This parameter only applies to CLKMODE x4. The RESET signal is not connected internally to the clock PLL circuit. The PLL, however, may need up to 250 µs to stabilize following device powerup or after PLL configuration has been changed. During that time, RESET must be asserted to ensure proper device operation. See the clock PLL section for PLL lock times.

Switching Characteristics During Reset⁽¹⁾

(see Figure 25)

NO.		PARAMETER	MIN	MAX	UNIT
2	t _{R(RESET)}	Response time to change of value in RESET signal	1 ⁽²⁾		CLKOUT1 cycles
3	t _{d(CKO1H} -CKO2IV)	Delay time, CLKOUT1 high to CLKOUT2 invalid	-1 ⁽²⁾		ns
4	t _d (CKO1H–CKO2V)	Delay time, CLKOUT1 high to CLKOUT2 valid		10 ⁽²⁾	ns
5	t _d (CKO1H-SDCLKIV)	Delay time, CLKOUT1 high to SDCLK invalid	-1 ⁽²⁾		ns
6	t _d (CKO1H-SDCLKV)	Delay time, CLKOUT1 high to SDCLK valid		10 ⁽²⁾	ns
7	t _d (CKO1H-SSCKIV)	Delay time, CLKOUT1 high to SSCLK invalid	-1 ⁽²⁾		ns
8	t _{d(CKO1H} -SSCKV)	Delay time, CLKOUT1 high to SSCLK valid		10 ⁽²⁾	ns
9	t _{d(CKO1H} LOWIV)	Delay time, CLKOUT1 high to low group invalid	-1 ⁽²⁾		ns
10	t _{d(CKO1H} LOWV)	Delay time, CLKOUT1 high to low group valid		10 ⁽²⁾	ns
11	t _{d(CKO1H} HIGHIV)	Delay time, CLKOUT1 high to high group invalid	-1 ⁽²⁾		ns
12	t _{d(CKO1H} HIGHV)	Delay time, CLKOUT1 high to high group valid		10 ⁽²⁾	ns
13	t _{d(CKO1H-ZHZ)}	Delay time, CLKOUT1 high to Z group high impedance	-1 ⁽²⁾		ns
14	t _{d(CKO1H-ZV)}	Delay time, CLKOUT1 high to Z group valid		10 ⁽²⁾	ns

⁽¹⁾ Low group consists of: IACK, INUM[3:0], DMAC[3:0], PD, TOUT0, and TOUT1. High group consists of: HRDY and HINT.

(2) This parameter is not tested

Z group consists of: EA[21:2], ED[31:0], CE[3:0], BE[3:0], ARE, AWE, AOE, SSADS, SSOE, SSWE, SDA10, SDRAS, SDCAS, SDWE, HD[15:0], CLKX0, CLKX1, FSX0, FSX1, DX0, DX1, CLKR0, CLKR1, FSR0, and FSR1.



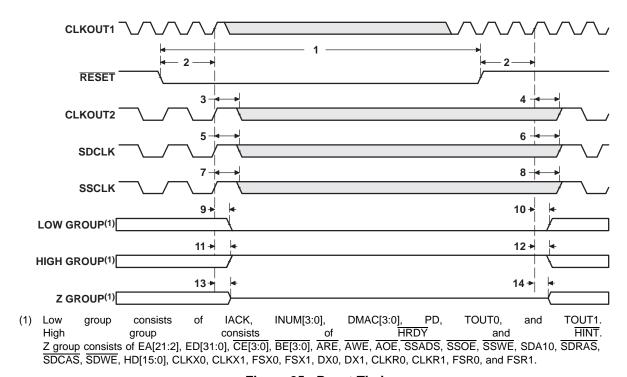


Figure 25. Reset Timing



EXTERNAL INTERRUPT/RESET TIMING

Timing Requirements for Interrupt Response Cycles⁽¹⁾ (2)

(see Figure 26)

NO.		MIN	MAX	UNIT
2	$t_{w(ILOW)}$ Width of the interrupt pulse low	2P ⁽³⁾		ns
3	$t_{w(IHIGH)}$ Width of the interrupt pulse high	2P ⁽³⁾		ns

- Interrupt signals are synchronized internally and are potentially recognized one cycle later if setup and hold times are violated. Thus, they can be connected to asynchronous inputs.
- (2) P = 1/CPU clock frequency in ns. For example, when running parts at 140 MHz, use P = 7 ns.
- (3) This parameter is not tested.

Switching Characteristics During Interrupt Response Cycles⁽¹⁾

(see Figure 26)

NO.		PARAMETER	MIN	MAX	UNIT
1	t _{R(EINTH-IACKH)}	Response time, EXT_INTx high to IACK high	9P		ns
4	t _{d(CKO2L-IACKV)}	Delay time, CLKOUT2 low to IACK valid	-0.5P	13 – 0.5P	ns
5	t _{d(CKO2L-INUMV)}	Delay time, CLKOUT2 low to INUMx valid		10 - 0.5P	ns
6	t _{d(CKO2L-INUMIV)}	Delay time, CLKOUT2 low to INUMx invalid	-0.5P		ns

(1) P = 1/CPU clock frequency in ns. For example, when running parts at 140 MHz, use P = 7 ns. When the PLL is used (CLKMODE x4), 0.5P = 1/(2 x CPU clock frequency). For CLKMODE x1: 0.5P = PH, where PH is the high period of CLKIN.

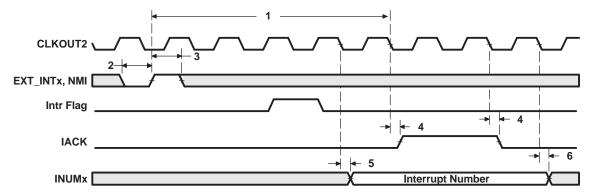


Figure 26. Interrupt Timing

HOST-PORT INTERFACE TIMING

Timing Requirements for Host-Port Interface Cycles (1) (2)

(see Figure 27, Figure 28, Figure 29, and Figure 30)

NO.			MIN	MAX	UNIT
1	t _{su(SEL-HSTBL)}	Setup time, select signals (3) valid before HSTROBE low	4		ns
2	t _{h(HSTBL} SEL)	Hold time, select signals (3) valid after HSTROBE low	2		ns
3	t _{w(HSTBL)}	Pulse duration, HSTROBE low	2P ⁽⁴⁾		ns
4	t _{w(HSTBH)}	Pulse duration, HSTROBE high between consecutive accesses	2P ⁽⁴⁾		ns
10	t _{su(SEL-HASL)}	Setup time, select signals (3) valid before HAS low	4		ns
11	t _{h(HASL-SEL)}	Hold time, select signals (3) valid after HAS low	2		ns
12	t _{su(HDV-HSTBH)}	Setup time, host data valid before HSTROBE high	3		ns
13	t _{h(HSTBH-HDV)}	Hold time, host data valid after HSTROBE high	2		ns
14	t _{h(HRDYL} -HSTBL)	Hold time, HSTROBE low after HRDY low. HSTROBE should not be inactivated until HRDY is active (low); otherwise, HPI writes will not complete properly.	1 (4)		ns
18	t _{su(HASL-HSTBL)}	Setup time, HAS low before HSTROBE low	2 ⁽⁴⁾		ns
19	t _{h(HSTBL-HASL)}	Hold time, HAS low after HSTROBE low	2 ⁽⁴⁾		ns

- (1) HSTROBE refers to the following logical operation on HCS, HDS1, and HDS2: [NOT(HDS1 XOR HDS2)] OR HCS.
- (2) The effects of internal clock jitter are included at test. There is no need to adjust timing numbers for internal clock jitter. P = 1/CPU clock frequency in ns. For example, when running parts at 140 MHz, use P = 7 ns.
- (3) Select signals include: HCNTRL[1:0], HR/W, and HHWIL.
- (4) This parameter is not tested.

Switching Characteristics During Host-Port Interface Cycles (1) (2)

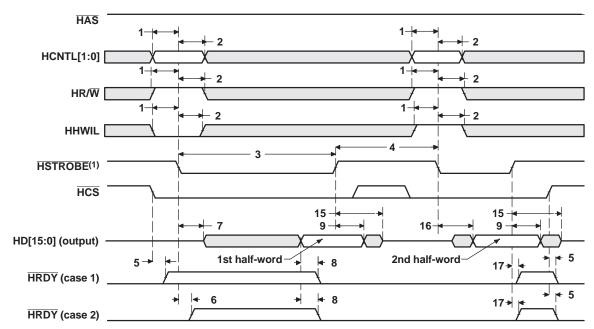
(see Figure 27, Figure 28, Figure 29, and Figure 30)

NO.		PARAMETER	MIN	MAX	UNIT
5	t _{d(HCS-HRDY)}	Delay time, HCS to HRDY (3)	1	12	ns
6	t _{d(HSTBL-HRDYH)}	Delay time, HSTROBE low to HRDY high (4)	1	12	ns
7	t _{oh(HSTBL-HDLZ)}	Output hold time, HD low impedance after $\overline{\mbox{HSTROBE}}$ low for an HPI read	4 ⁽⁵⁾		ns
8	t _{d(HDV-HRDYL)}	Delay time, HD valid to HRDY low	P – 3 ⁽⁵⁾	P + 3 ⁽⁵⁾	ns
9	t _{oh(HSTBH-HDV)}	Output hold time, HD valid after HSTROBE high	3	12	ns
15	t _{d(HSTBH-HDHZ)}	Delay time, HSTROBE high to HD high impedance	3 ⁽⁵⁾	12 ⁽⁵⁾	ns
16	t _{d(HSTBL-HDV)}	Delay time, HSTROBE low to HD valid	3	12	ns
17	t _{d(HSTBH-HRDYH)}	Delay time, HSTROBE high to HRDY high (6)	1	12	ns

- (1) HSTROBE refers to the following logical operation on HCS, HDS1, and HDS2: [NOT(HDS1 XOR HDS2)] OR HCS.
- (2) The effects of internal clock jitter are included at test. There is no need to adjust timing numbers for internal clock jitter. P = 1/CPU clock frequency in ns. For example, when running parts at 140 MHz, use P = 7 ns.
- (3) HCS enables HRDY, and HRDY is always low when HCS is high. The case where HRDY goes high when HCS falls indicates that HPI is busy completing a previous HPID write or READ with autoincrement.
- (4) This parameter is used during an HPID read. At the beginning of the first half–word transfer on the falling edge of HSTROBE, the HPI sends the request to the DMA auxiliary channel, and HRDY remains high until the DMA auxiliary channel loads the requested data into HPID.
- (5) This parameter is not tested.
- (6) This parameter is used after the second half-word of an HPID write or autoincrement read. HRDY remains low if the access is not an HPID write or autoincrement read. Reading or writing to HPIC or HPIA does not affect the HRDY signal.

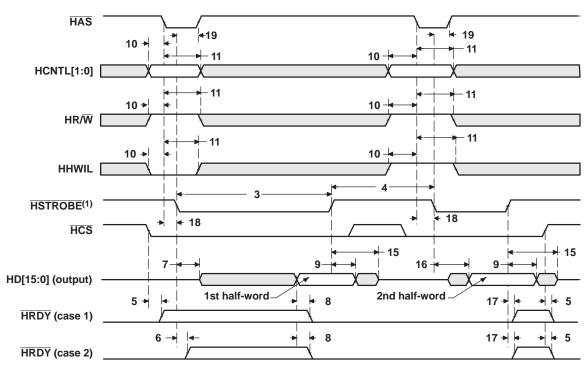
Product Folder Links: SMJ320C6701-SP





(1) HSTROBE refers to the following logical operation on HCS, HDS1, and HDS2: [NOT(HDS1 XOR HDS2)] OR HCS.

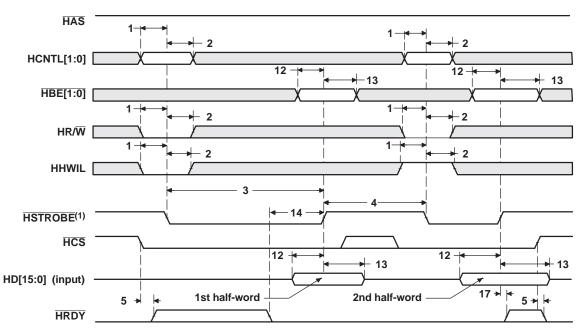
Figure 27. HPI Read Timing (HAS Not Used, Tied High)



(1) HSTROBE refers to the following logical operation on HCS, HDS1, and HDS2: [NOT(HDS1 XOR HDS2)] OR HCS.

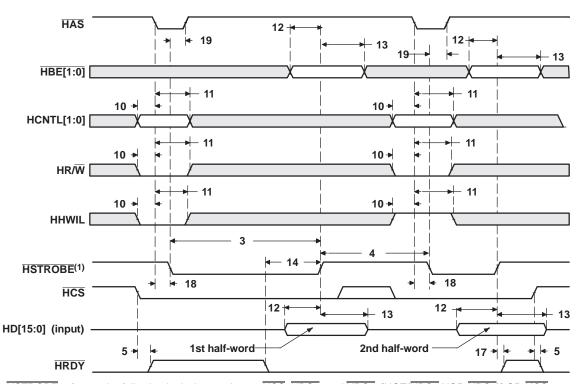
Figure 28. HPI Read Timing (HAS Used)





(1) $\overline{\text{HSTROBE}}$ refers to the following logical operation on $\overline{\text{HCS}}$, $\overline{\text{HDS1}}$, and $\overline{\text{HDS2}}$: [NOT($\overline{\text{HDS1}}$ XOR $\overline{\text{HDS2}}$)] OR $\overline{\text{HCS}}$.

Figure 29. HPI Write Timing (HAS Not Used, Tied High)



(1) $\overline{\text{HSTROBE}}$ refers to the following logical operation on $\overline{\text{HCS}}$, $\overline{\text{HDS1}}$, and $\overline{\text{HDS2}}$: [NOT($\overline{\text{HDS1}}$ XOR $\overline{\text{HDS2}}$)] OR $\overline{\text{HCS}}$.

Figure 30. HPI Write Timing (HAS Used)



MULTICHANNEL BUFFERED SERIAL PORT TIMING

Timing Requirements for McBSP⁽¹⁾ (2)

(see Figure 31)

NO.				MIN	MAX	UNIT
2	t _{c(CKRX)}	Cycle time, CLKR/X	CLKR/X ext	2P ⁽³⁾		ns
3	t _{w(CKRX)}	Pulse duration, CLKR/X high or CLKR/X low	CLKR/X ext	P – 1 ⁽³⁾		ns
5		Catual time automal ECD high before CLVD law	CLKR int	13 ⁽³⁾		
5	t _{su(FRH} CKRL)	Setup time, external FSR high before CLKR low	CLKR ext	4		ns
6		Lold time outernal ECD high ofter CLVD law	CLKR int	7 ⁽³⁾		20
О	t _{h(CKRL-FRH)}	Hold time, external FSR high after CLKR low	CLKR ext	4		ns
7		Catus time DD valid before CLVD law	CLKR int	10		20
1	t _{su(DRV-CKRL)}	Setup time, DR valid before CLKR low	CLKR ext	1		ns
8			CLKR int	4		20
0	th(CKRL-DRV)	Hold time, DR valid after CLKR low	CLKR ext	4		ns
10		Catual time, outsmal ECV high hafers CLIVV law	CLKX int	13 ⁽³⁾		
10 t	t _{su(FXH} CKXL)	Setup time, external FSX high before CLKX low	CLKX ext	4		ns
44		Held time a sutamed FCV high after CLKV law.	CLKX int	7 ⁽³⁾		
11	th(CKXL-FXH)	Hold time, external FSX high after CLKX low	CLKX ext	3		ns

⁽¹⁾ P = 1/CPU clock frequency in ns. For example, when running parts at 140 MHz, use P = 7 ns.

18

Product Folder Links: SMJ320C6701-SP

⁽²⁾ CLKRP = CLKXP = FSRP = FSXP = 0 in the pin control register (PCR). If polarity of any of the signals is inverted, then the timing references of that signal are also inverted.

⁽³⁾ This parameter is not tested.



Switching Characteristics for McBSP⁽¹⁾ (2) (3)

(see Figure 31)

NO.		PARAMETER		MIN	MAX	UNIT
1	t _{d(CKSH} -CKRXH)	Delay time, CLKS high to CLKR/X high for internal CLKR/X generated from CLKS input		3	15	ns
2	t _{c(CKRX)}	Cycle time, CLKR/X	CLKR/X int	2P		ns
3	t _{w(CKRX)}	Pulse duration, CLKR/X high or CLKR/X low	CLKR/X int	C - 1 ⁽⁴⁾	C + 1 ⁽⁴⁾	ns
4	t _{d(CKRH-FRV)}	Delay time, CLKR high to internal FSR valid	CLKR int	-4	4	ns
0	Deleviting Olivinish	Deleviting OHKV bights internal FOV wells	CLKX int	-4	5	
9	t _d (CKXH–FXV)	Delay time, CLKX high to internal FSX valid	CLKX ext	3 ⁽⁵⁾	16 ⁽⁵⁾	ns
40		Disable time, DX high impedance following last data bit	CLKX int	-3 ⁽⁵⁾	2 ⁽⁵⁾	
12	t _{dis} (CKXH–DXHZ)	from CLKX high	CLKX ext	2 ⁽⁵⁾	9 ⁽⁵⁾	ns
40		Deleviting OHKV Edit to DV vollet	CLKX int	-2	4	
13	t _d (CKXH–DXV)	Delay time, CLKX high to DX valid.	CLKX ext	3	16	ns
		Delay time, FSX high to DX valid.	FSX int	-2 ⁽⁵⁾	4 ⁽⁵⁾	
14	t _{d(FXH-DXV)}	ONLY applies when in data delay 0 (XDATDLY = 00b) mode.	FSX ext	2 ⁽⁵⁾	10 ⁽⁵⁾	ns

⁽¹⁾ CLKRP = CLKXP = FSRP = FSXP = 0 in the pin control register (PCR). If polarity of any of the signals is inverted, then the timing references of that signal are also inverted.

Minimum delay times also represent minimum output hold times.

P = 1/CPU clock frequency in ns. For example, when running parts at 140 MHz, use P = 7 ns.

S = sample rate generator input clock = P if CLKSM = 1 (P = 1/CPU clock frequency) = sample rate generator input clock = P_clks if CLKSM = 0 (P_clks = CLKS period) H = CLKX high pulse width = (CLKGDV/2 + 1) * S if CLKGDV is even

^{= (}CLKGDV + 1)/2 * S if CLKGDV is odd or zero

L = CLKX low pulse width = (CLKGDV/2) * S if CLKGDV is even

^{= (}CLKGDV + 1)/2 * S if CLKGDV is odd or zero

⁽⁵⁾ This parameter is not tested.



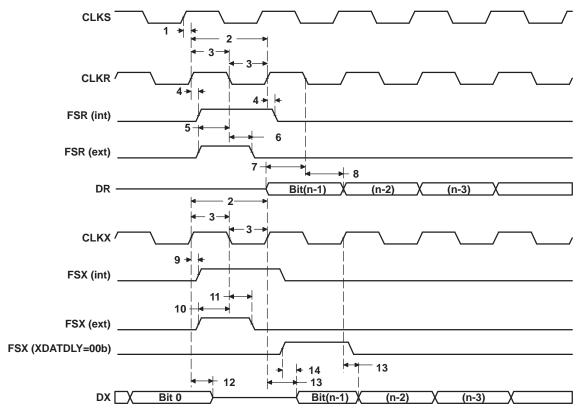


Figure 31. McBSP Timing

Timing Requirements for FSR When GSYNC = 1

(see Figure 32)

(,				
NO.			MIN	MAX	UNIT
1	tsu(FRH-CKSH)	Setup time, FSR high before CLKS high	4 ⁽¹⁾		ns
2	th(CKSH-FRH)	Hold time, FSR high after CLKS high	4 ⁽¹⁾		ns

(1) This parameter is not tested.

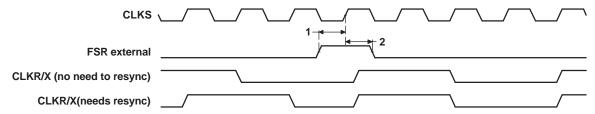


Figure 32. FSR Timing When GSYNC = 1

Timing Requirements for McBSP as SPI Master or Slave: CLKSTP = 10b, CLKXP = $0^{(1)}$ (2)

(seeFigure 33)

NO			MASTE	ER .	SLAVE		UNIT	
NO.			MIN	MAX	MIN	MAX	UNII	
4	t _{su(DRV-CKXL)}	Setup time, DR valid before CLKX low	12		2 – 3P		ns	
5	t _{h(CKXL-DRV)}	Hold time, DR valid after CLKX low	4		5 + 6P		ns	

- The effects of internal clock jitter are included at test. There is no need to adjust timing numbers for internal clock jitter. P = 1/CPU clock frequency in ns. For example, when running parts at 140 MHz, use P = 7 ns.
- For all SPI slave modes, CLKG is programmed as 1/2 of the CPU clock by setting CLKSM = CLKGDV = 1.

Switching Characteristics for McBSP as SPI Master or Slave: CLKSTP = 10b, CLKXP=0⁽¹⁾ (2)

(see Figure 33)

NO.		PARAMETER		MASTER (3)		SLAVE		
NO.		PARAMETER	MIN	MAX	MIN	MAX	UNIT	
1	t _{h(CKXL-FXL)}	Hold time, FSX low after CLKX low (4)	T – 4	T + 4			ns	
2	t _{d(FXL-CKXH)}	Delay time, FSX low to CLKX high (5)	L – 4	L + 4			ns	
3	t _{d(CKXH-DXV)}	Delay time, CLKX high to DX valid	-4	4	3P + 1	5P + 17	ns	
6	t _{dis(CKXL-DXHZ)}	Disable time, DX high impedance following last data ♦ bit from CLKX low	L – 2 ⁽⁶⁾	L + 3 ⁽⁶⁾			ns	
7	t _{dis(FXH-DXHZ)}	Disable time, DX high impedance following last data � bit from FSX high			P + 4 ⁽⁶⁾	3P + 17 ⁽⁶⁾	ns	
8	t _{d(FXL-DXV)}	Delay time, FSX low to DX valid			2P + 1	4P + 13	ns	

- The effects of internal clock jitter are included at test. There is no need to adjust timing numbers for internal clock jitter. P = 1/CPU clock frequency in ns. For example, when running parts at 140 MHz, use P = 7 ns.
- For all SPI slave modes, CLKG is programmed as 1/2 of the CPU clock by setting CLKSM = CLKGDV = 1.
- S = sample rate generator input clock = P if CLKSM = 1 (P = 1/CPU clock frequency)
 - = sample rate generator input clock = P_clks if CLKSM = 0 (P_clks = CLKS period)
 - T = CLKX period = (1 + CLKGDV) * S
 - H = CLKX high pulse width = (CLKGDV/2 + 1) * S if CLKGDV is even
 - = (CLKGDV + 1)/2 * S if CLKGDV is odd or zero
 - L = CLKX low pulse width = (CLKGDV/2) * S if CLKGDV is even
 - = (CLKGDV + 1)/2 * S if CLKGDV is odd or zero
- FSRP = FSXP = 1. As a SPI master, FSX is inverted to provide active-low slave-enable output. As a slave, the active-low signal input on FSX and FSR is inverted before being used internally. CLKXM = FSXM = 1, CLKRM = FSRM = 0 for master McBSP

 - CLKXM = CLKRM = FSXM = FSRM = 0 for slave McBSP
- FSX should be low before the rising edge of clock to enable slave devices and then begin a SPI transfer at the rising edge of the master clock (CLKX).
- This parameter is not tested.

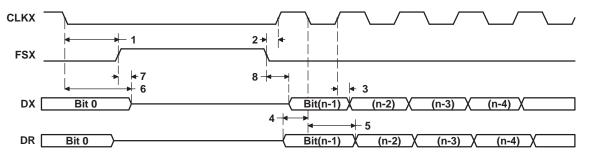


Figure 33. McBSP Timing as SPI Master or Slave: CLKSTP = 10b, CLKXP = 0

Timing Requirements SPI Master or Slave: CLKSTP = 11b, CLKXP = 0⁽¹⁾ (1)

(see Figure 34)

The effects of internal clock jitter are included at test. There is no need to adjust timing numbers for internal clock jitter. P = 1/CPU clock frequency in ns. For example, when running parts at 140 MHz, use P = 7 ns.

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Timing Requirements SPI Master or Slave: CLKSTP = 11b, CLKXP = 0⁽¹⁾ (continued)

(see Figure 34)

NO.			MASTE	MASTER		SLAVE	
NO.			MIN	MAX	MIN	MAX	UNIT
4	t _{su(DRV-CKXH)}	Setup time, DR valid before CLKX high	12		2 – 3P		ns
5	t _{h(CKXH-DRV)}	Hold time, DR valid after CLKX high	4		5 + 6P		ns

Switching Characteristics for McBSP as SPI Master or Slave: CLKSTP = 11b, CLKXP = 0⁽¹⁾ (2)

(see Figure 34)

NO.		PARAMETER		MASTER (3)		SLAVE		
NO.		PARAMETER	MIN	MAX	MIN	MAX	UNIT	
1	t _{h(CKXL-FXL)}	Hold time, FSX low after CLKX low (4)	L – 4	L + 4			ns	
2	t _{d(FXL-CKXH)}	Delay time, FSX low to CLKX high (5)	T – 4	T + 4			ns	
3	t _{d(CKXL-DXV)}	Delay time, CLKX low to DX valid	-4	4	3P + 1	5P + 17	ns	
6	$t_{dis(CKXL-DXHZ)}$	Disable time, DX high impedance following last data bit from CLKX low	-2 ⁽⁶⁾	4 ⁽⁶⁾	3P + 4 ⁽⁶⁾	5P + 17 ⁽⁶⁾	ns	
7	t _{d(FXL-DXV)}	Delay time, FSX low to DX valid	H – 2 ⁽⁶⁾	H + 3 ⁽⁶⁾	2P + 1	4P + 13	ns	

- (1) The effects of internal clock jitter are included at test. There is no need to adjust timing numbers for internal clock jitter. P = 1/CPU clock frequency in ns. For example, when running parts at 140 MHz, use P = 7 ns.
- (2) For all SPI slave modes, CLKG is programmed as 1/2 of the CPU clock by setting CLKSM = CLKGDV = 1.
- (3) S = sample rate generator input clock = P if CLKSM = 1 (P = 1/CPU clock frequency)
 - = sample rate generator input clock = P_clks if CLKSM = 0 (P_clks = CLKS period)
 - T = CLKX period = (1 + CLKGDV) * S
 - H = CLKX high pulse width = (CLKGDV/2 + 1) * S if CLKGDV is even
 - = (CLKGDV + 1)/2 * S if CLKGDV is odd or zero
 - L = CLKX low pulse width = (CLKGDV/2) * S if CLKGDV is even
 - = (CLKGDV + 1)/2 * S if CLKGDV is odd or zero
- (4) FSRP = FSXP = 1. As a SPI master, FSX is inverted to provide active-low slave-enable output. As a slave, the active-low signal input on FSX and FSR is inverted before being used internally.
 - CLKXM = FSXM = 1, CLKRM = FSRM = 0 for master McBSP
 - CLKXM = CLKRM = FSXM = FSRM = 0 for slave McBSP
- (5) FSX should be low before the rising edge of clock to enable slave devices and then begin a SPI transfer at the rising edge of the master clock (CLKX).
- (6) This parameter is not tested.

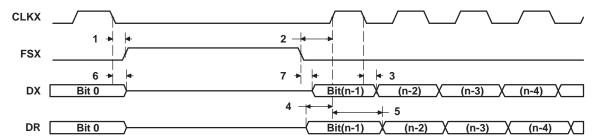


Figure 34. McBSP Timing as SPI Master or Slave: CLKSTP = 11b, CLKXP = 0

Timing Requirements for MCBSP as SPI Master or Slave: CLKSTOP = 10b, CLKXP = 1⁽¹⁾ (2)

(see Figure 35)

NO.			MAST	ER	SLAVE		UNIT
NO.			MIN	MAX	MIN	MAX	
4	t _{su(DRV-CKXH)}	Setup time, DR valid before CLKX high	12		2 – 3P		ns
5	t _{h(CKXH-DRV)}	Hold time, DR valid after CLKX high	4		5 + 6P		ns

- The effects of internal clock jitter are included at test. There is no need to adjust timing numbers for internal clock jitter. P = 1/CPU clock frequency in ns. For example, when running parts at 140 MHz, use P = 7 ns.
- For all SPI slave modes, CLKG is programmed as 1/2 of the CPU clock by setting CLKSM = CLKGDV = 1.

Switching Characteristics for McBSP as SPI Master or Slave: CLKSTP = 10b, CLKXP = 1⁽¹⁾ (2)

(see Figure 35)

NO.		PARAMETER		MASTER (3)		SLAVE	
NO.		PARAMETER	MIN	MAX	MIN	MAX	UNIT
1	t _{h(CKXH-FXL)}	Hold time, FSX low after CLKX high (4)	T – 4	T + 4			ns
2	t _{d(FXL-CKXL)}	Delay time, FSX low to CLKX low ⁽⁵⁾	H – 4	H + 4			ns
3	t _{d(CKXL-DXV)}	Delay time, CLKX low to DX valid	-4	4	3P + 1	5P + 17	ns
6	$t_{dis(CKXH-DXHZ)}$	Disable time, DX high impedance following last data bit from CLKX high	H – 2 ⁽⁶⁾	H + 3 ⁽⁶⁾			ns
7	$t_{dis(FXH-DXHZ)}$	Disable time, DX high impedance following last data bit from FSX high			P + 4 ⁽⁶⁾	3P + 17 ⁽⁶⁾	ns
8	t _{d(FXL-DXV)}	Delay time, FSX low to DX valid			2P + 1	4P + 13	ns

- (1) The effects of internal clock jitter are included at test. There is no need to adjust timing numbers for internal clock jitter. P = 1/CPU clock frequency in ns. For example, when running parts at 140 MHz, use P = 7 ns.
- For all SPI slave modes, CLKG is programmed as 1/2 of the CPU clock by setting CLKSM = CLKGDV = 1.
- S = sample rate generator input clock = P if CLKSM = 1 (P = 1/CPU clock frequency)
 - = sample rate generator input clock = P_clks if CLKSM = 0 (P_clks = CLKS period)
 - T = CLKX period = (1 + CLKGDV) * S
 - H = CLKX high pulse width = (CLKGDV/2 + 1) * S if CLKGDV is even
 - = (CLKGDV + 1)/2 * S if CLKGDV is odd or zero
 - L = CLKX low pulse width = (CLKGDV/2) * S if CLKGDV is even
 - = (CLKGDV + 1)/2 * S if CLKGDV is odd or zero
- FSRP = FSXP = 1. As a SPI master, FSX is inverted to provide active-low slave-enable output. As a slave, the active-low signal input on FSX and FSR is inverted before being used internally. CLKXM = FSXM = 1, CLKRM = FSRM = 0 for master McBSP
 - CLKXM = CLKRM = FSXM = FSRM = 0 for slave McBSP
- FSX should be low before the rising edge of clock to enable slave devices and then begin a SPI transfer at the rising edge of the master clock (CLKX).
- This parameter is not tested.

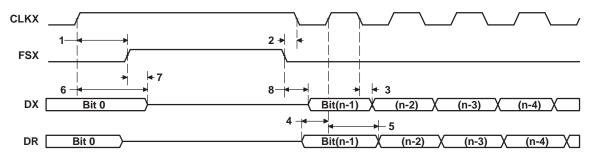


Figure 35. McBSP Timing as SPI Master or Slave: CLKSTP = 10b, CLKXP = 1

Timing Requirements for McBSP as SPI Master or Slave: CLKSTOP = 11b, CLKXP = 1(1) (2)

(see Figure 36)

(1) The effects of internal clock jitter are included at test. There is no need to adjust timing numbers for internal clock jitter. P = 1/CPU clock frequency in ns. For example, when running parts at 140 MHz, use P = 7 ns.

For all SPI slave modes, CLKG is programmed as 1/2 of the CPU clock by setting CLKSM = CLKGDV = 1.



Timing Requirements for McBSP as SPI Master or Slave: CLKSTOP = 11b, CLKXP = $1^{(1)}$ (continued)

(see Figure 36)

NO.			MASTE	:R	SLAVE		UNIT
NO.			MIN	MAX	MIN	MAX	UNIT
4	t _{su(DRV-CKXL)}	Setup time, DR valid before CLKX low	12		2 - 3P		ns
5	t _{h(CKXL-DRV)}	Hold time, DR valid after CLKX low	4		5 + 6P		ns

Switching Characteristics for McBSP as SPI Master or Slave: CLKSTP = 11b, CLKXP = 1(1) (2)

(see Figure 36)

NO.		PARAMETER		MASTER (3)		SLAVE	
NO.		PARAMETER	MIN	MAX	MIN	MAX	UNIT
1	t _{h(CKXH-FXL)}	Hold time, FSX low after CLKX high (4)	H – 4	H + 4			ns
2	t _{d(FXL-CKXL)}	Delay time, FSX low to CLKX low ⁽⁵⁾	T – 4	T + 4			ns
3	t _{d(CKXH-DXV)}	Delay time, CLKX high to DX valid	-4	4	3P + 1	5P + 17	ns
6	t _{dis(CKXH-DXHZ)}	Disable time, DX high impedance following last data bit from CLKX high	-2 ⁽⁶⁾	4 ⁽⁶⁾	3P + 4 ⁽⁶⁾	5P + 17 ⁽⁶⁾	ns
7	t _{d(FXL-DXV)}	Delay time, FSX low to DX valid	L - 2 ⁽⁶⁾	L + 3 ⁽⁶⁾	2P + 1	4P + 13	ns

- (1) The effects of internal clock jitter are included at test. There is no need to adjust timing numbers for internal clock jitter. P = 1/CPU clock frequency in ns. For example, when running parts at 140 MHz, use P = 7 ns.
- (2) For all SPI slave modes, CLKG is programmed as 1/2 of the CPU clock by setting CLKSM = CLKGDV = 1.
- (3) S = sample rate generator input clock = P if CLKSM = 1 (P = 1/CPU clock frequency)
 - = sample rate generator input clock = P_clks if CLKSM = 0 (P_clks = CLKS period)
 - T = CLKX period = (1 + CLKGDV) * S
 - H = CLKX high pulse width = (CLKGDV/2 + 1) * S if CLKGDV is even
 - = (CLKGDV + 1)/2 * S if CLKGDV is odd or zero
 - L = CLKX low pulse width = (CLKGDV/2) * S if CLKGDV is even
 - = (CLKGDV + 1)/2 * S if CLKGDV is odd or zero
- (4) FSRP = FSXP = 1. As a SPI master, FSX is inverted to provide active-low slave-enable output. As a slave, the active-low signal input on FSX and FSR is inverted before being used internally.
 - CLKXM = FSXM = 1, CLKRM = FSRM = 0 for master McBSP
 - CLKXM = CLKRM = FSXM = FSRM = 0 for slave McBSP
- (5) FSX should be low before the rising edge of clock to enable slave devices and then begin a SPI transfer at the rising edge of the master clock (CLKX).
- (6) This parameter is not tested.

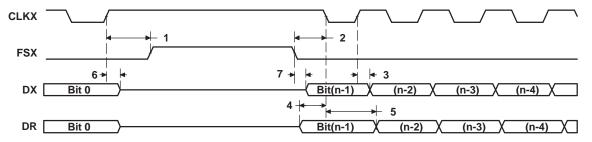


Figure 36. McBSP Timing as SPI Master or Slave: CLKSTP = 11b, CLKXP = 1

DMAC, TIMER, POWER-DOWN TIMING

Switching Characteristics for DMAC Outputs

(see Figure 37)

NO.	PARAMETER	MIN	MAX	UNIT
1	t _{d(CKO1H-DMACV)} Delay time, CLKOUT1 high to DMAC valid	2	11	ns



Figure 37. DMAC Timing

Timing Requirements for Timer Inputs⁽¹⁾

(see Figure 38)

NO.		MIN	MAX	UNIT
1	t _{w(TINPH)} Pulse duration, TINP high	2P		ns

⁽¹⁾ P = 1/CPU clock frequency in ns. For example, when running parts at 140 MHz, use P = 7 ns.

Switching Characteristics for Timer Outputs

(see Figure 38)

NO.	PARAMETER	MIN	MAX	UNIT
2	t _{d(CKO1H-TOUTV)} Delay time, CLKOUT1 high to TOUT valid	1	10	ns

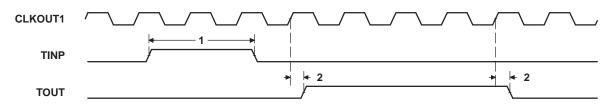


Figure 38. Timer Timing

Switching Characteristics for Power-Down Outputs

(seeFigure 39)

NO.	PARAMETER	MIN	MAX	UNIT	
1	t _{d(CKO1H-PDV)} Delay time, CLKOUT1 high to PD valid	1	9	ns	

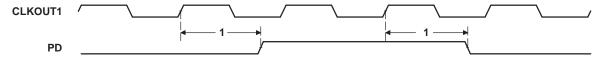


Figure 39. Power-Down Timing

Product Folder Links: SMJ320C6701-SP

JTAG TEST-PORT TIMING

Timing Requirements for JTAG Test Port

(see Figure 40)



Timing Requirements for JTAG Test Port (continued)

(see Figure 40)

NO.			MIN	MAX	UNIT
1	t _{c(TCK)} Cycle t	me, TCK	35		ns
3	t _{su(TDIV-TCKH)} Setup t	ime, TDI/TMS/TRST valid before TCK high	10		ns
4	t _{h(TCKH-TDIV)} Hold tir	ne, TDI/TMS/TRST valid after TCK high	9		ns

Switching Characteristics for JTAG Test Port

(see Figure 40)

ſ	NO.	PARAMETER	MIN	MAX	UNIT
	2	$t_{d(TCKL-TDOV)}$ Delay time, TCK low to TDO valid	-3 ⁽¹⁾	15 ⁽¹⁾	ns

(1) This parameter is not tested.

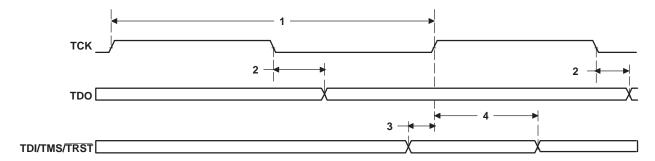


Figure 40. JTAG Test-Port Timing

www.ti.com 11-Nov-2025

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
5962-9866101VXA	Active	Production	CFCBGA (GLP) 429	40 JEDEC TRAY (5+1)	No	SNPB	N/A for Pkg Type	0 to 0	5962-9866101VX A SMV320C6701GLP W14
5962-9866101VXA.A	Active	Production	CFCBGA (GLP) 429	40 JEDEC TRAY (5+1)	No	SNPB	N/A for Pkg Type	0 to 0	5962-9866101VX A SMV320C6701GLP W14
5962-9866102VXA	Active	Production	CFCBGA (GLP) 429	40 JEDEC TRAY (5+1)	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9866102VX A SMV320C6701GLP M14
5962-9866102VXA.A	Active	Production	CFCBGA (GLP) 429	40 JEDEC TRAY (5+1)	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9866102VX A SMV320C6701GLP M14
5962-9866102VYC	Active	Production	FCLGA (ZMB) 429	40 JEDEC TRAY (5+1)	-	Call TI	N/A for Pkg Type	-55 to 125	5962-9866102VY C SMV320C6701ZMB M14
5962-9866102VYC.A	Active	Production	FCLGA (ZMB) 429	40 JEDEC TRAY (5+1)	-	Call TI	N/A for Pkg Type	-55 to 125	5962-9866102VY C SMV320C6701ZMB M14
SMV320C6701GLP/EM	Active	Production	CFCBGA (GLP) 429	1 TUBE	No	SNPB	N/A for Pkg Type	0 to 0	SMV320C6701GLP/EM EVAL ONLY
SMV320C6701GLP/EM.A	Active	Production	CFCBGA (GLP) 429	1 TUBE	No	SNPB	N/A for Pkg Type	0 to 0	SMV320C6701GLP/EM EVAL ONLY

⁽¹⁾ Status: For more details on status, see our product life cycle.

⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

PACKAGE OPTION ADDENDUM

www.ti.com 11-Nov-2025

- (3) RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.
- (4) Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.
- (5) MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.
- (6) Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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OTHER QUALIFIED VERSIONS OF SMJ320C6701-SP:

Catalog: SMJ320C6701

NOTE: Qualified Version Definitions:

Catalog - TI's standard catalog product



www.ti.com 23-Aug-2025

TRAY



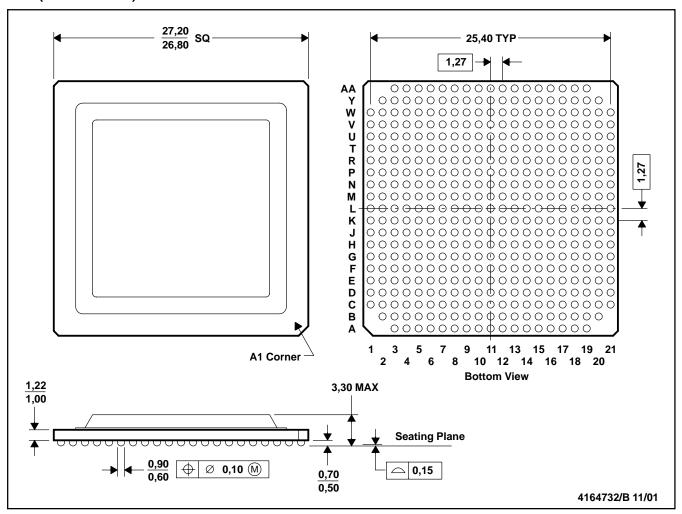
Chamfer on Tray corner indicates Pin 1 orientation of packed units.

*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	Unit array matrix	Max temperature (°C)	L (mm)	W (mm)	Κ0 (μm)	P1 (mm)	CL (mm)	CW (mm)
5962-9866101VXA	GLP	CFCBGA	429	40	4x10	150	315	135.9	7620	29.2	26.1	24.15
5962-9866101VXA.A	GLP	CFCBGA	429	40	4x10	150	315	135.9	7620	29.2	26.1	24.15
5962-9866102VXA	GLP	CFCBGA	429	40	4x10	150	315	135.9	7620	29.2	26.1	24.15
5962-9866102VXA.A	GLP	CFCBGA	429	40	4x10	150	315	135.9	7620	29.2	26.1	24.15
5962-9866102VYC	ZMB	FCLGA	429	40	4x10	150	315	135.9	7620	29.2	26.1	24.15
5962-9866102VYC.A	ZMB	FCLGA	429	40	4x10	150	315	135.9	7620	29.2	26.1	24.15
SMV320C6701GLP/EM	GLP	CFCBGA	429	1	4x10	150	315	135.9	7620	29.2	26.1	24.15
SMV320C6701GLP/ EM.A	GLP	CFCBGA	429	1	4x10	150	315	135.9	7620	29.2	26.1	24.15

GLP (S-CBGA-N429)

CERAMIC BALL GRID ARRAY

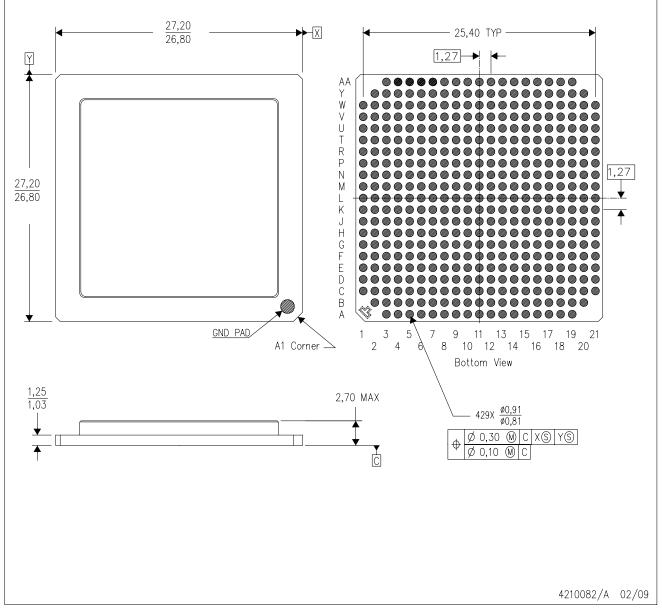


NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MO-156
- D. Flip chip application only

ZMB (S-CLGA-N429)

CERAMIC LAND GRID ARRAY



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Flip chip application only.
- D. All Ball Pads are Gold plated.



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